Service Manual



Tektronix

11A16 Two-Channel Current Amplifier 070-7764-00

Warning

The servicing instructions are for use by qualified personnel only. To avoid personal injury, do not perform any servicing unless you are qualified to do so. Refer to the Safety Summary prior to performing service.

Please check for change information at the rear of this manual.

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Instrument Serial Numbers

Each instrument manufactured by Tektronix has a serial number on a panel insert or tag, or stamped on the chassis. The first letter in the serial number designates the country of manufacture. The last five digits of the serial number are assigned sequentially and are unique to each instrument. Those manufactured in the United States have six unique digits. The country of manufacture is identified as follows:

| B010000 | Tektronix, Inc., Beaverton, Oregon, USA |
|---------|---|
| E200000 | Tektronix United Kingdom, Ltd., London |

J300000 Sony/Tektronix, Japan

H700000 Tektronix Holland, NV, Heerenveen, The Netherlands

Instruments manufactured for Tektronix by external vendors outside the United States are assigned a two digit alpha code to identify the country of manufacture (e.g., JP for Japan, HK for Hong Kong, IL for Israel, etc.).

Tektronix, Inc., P.O. Box 500, Beaverton, OR 97077

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Tektronix warrants that this product will be free from defects in materials and workmanship for a period of one (1) year from the date of shipment. If any such product proves defective during this warranty period, Tektronix, at its option, either will repair the defective product without charge for parts and labor, or will provide a replacement in exchange for the defective product.

In order to obtain service under this warranty, Customer must notify Tektronix of the defect before the expiration of the warranty period and make suitable arrangements for the performance of service. Customer shall be responsible for packaging and shipping the defective product to the service center designated by Tektronix, with shipping charges prepaid. Tektronix shall pay for the return of the product to Customer if the shipment is to a location within the country in which the Tektronix service center is located. Customer shall be responsible for paying all shipping charges, duties, taxes, and any other charges for products returned to any other locations.

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General Information

This reference provides service information and test procedures for the 11A16 Two-Channel Current Amplifier. It contains information necessary for qualified service personnel to check, maintain, and troubleshoot the 11A16.

Checking the 11A16 involves performing a sequence of Check and Adjustment procedures. These procedures verify that the 11A16 is operating correctly.

The majority of Troubleshooting is based upon internal diagnostics that the mainframe and 11A16 perform automatically. Some visual and mechanical troubleshooting may be necessary. Both diagnostic techniques isolate problems to the field replaceable unit (FRU) level. Once the faulty FRU is identified, you can use the Corrective Maintenance section to remove and replace the faulty FRU.

The 11A16 is a two-channel, medium-bandwidth, current amplifier that plugs into any of the 11000 or DSA 600 Series mainframes that use amplifiers. Commands from the mainframe control all 11A16 functions except probe degauss. For example:

- Any combination of the two input channels can be provided to the host mainframe.
- Signals can be independently inverted and summed.
- Channel bandwidth limiting can be switched between 20 and 50 MHz.

The front panel of the 11A16 has two buttons and an LED indicator for each input channel. Other controls and status indicators are located on the mainframe. Each channel has a 12-pin input connector. When a probe is connected to the input, the 11A16 detects the probe-encoding information, to select the appropriate scaling.

This reference contains the following sections:

- General Information describes information that you should know about the 11A16 before you service it, such as safety information, installation and removal, available options, and packaging suggestions.
- Checks and Adjustments provides you with procedures to examine the measurement limits and electrical specifications of the 11A16.
- Maintenance contains information necessary to do preventive maintenance, remove/replace field replaceable units (FRUs), and diagnose faulty FRUs.
- Theory of Operation describes the general operation and signal path of the 11A16.
- Replaceable Parts provides you with a complete list of replaceable electrical and mechanical parts found on the 11A16.

11A16 Service Reference 1-1

Safety Summary

This general safety information is directed to operators and service personnel. Specific warnings and cautions will be found throughout the manual, but may not appear in this summary.

Terms in Manuals

CAUTION statements in manuals identify conditions or actions that could damage the equipment or other property.

WARNING statements in manuals identify conditions or actions that could result in personal injury or loss of life.

Terms on Equipment

CAUTION warns you of possible hazards to the equipment or yourself though you are not exposed as you read the marking.

DANGER warns of a personal injury hazard as you read the marking.

Symbols in Manuals



Static Sensitive Devices

Symbols on Equipment



DANGER High Voltage



Protective ground (earth) terminal



ATTENTION Refer to manual

Power Source

This 11A16 is intended to operate in a mainframe connected to a power source that will not apply more than 250 V rms between the supply conductors or between either a supply conductor and ground. A protective ground connection, through the grounding conductor in the mainframe power cord, is essential for safe system operation.

Grounding the 11A16

The 11A16 is grounded through the grounding conductor of the mainframe power cord. To avoid electric shock, plug the mainframe power cord into a properly wired receptacle before installing the 11A16. A protective ground connection, through the grounding conductor in the mainframe power cord, is essential for safe operation.

Danger Arising from Loss of Ground

Upon loss of the protective-ground connection, all accessible conductive parts (including knobs and controls that may appear to be insulators), can render an electrical shock.

Do Not Operate in Explosive Atmospheres

To avoid explosion, do not operate this product in an atmosphere of explosive gasses.

Do Not Service Alone

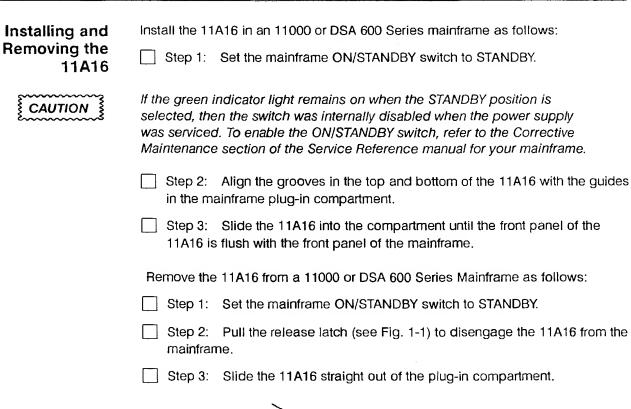
Do not perform internal service or adjustment of this product unless another person capable of rendering first aid and resuscitation is present.

Use Care When Servicing with Power On

Dangerous voltages exist at several points in this product. To avoid personal injury, do not touch exposed connections or components while the power is on.

Disconnect the power before removing protective panels, or replacing components.

11A16 Service Reference 1-3



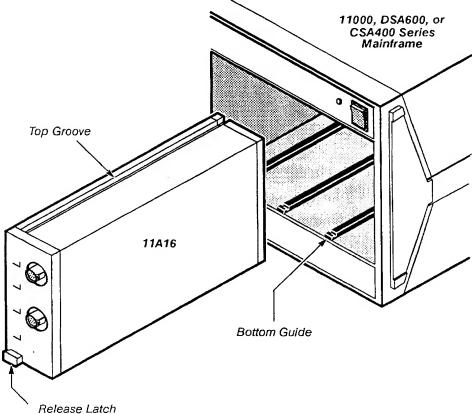


Figure 1-1 — Installing and Removing the 11A16

Memory Backup Power for the 11A16

The nonvolatile RAM (NVRAM) within the 11A16 allows the data in memory to be retained when the 11A16 is powered-down and removed. The NVRAM stores system-configuration data such as the 11A16, mainframe, and probe identification numbers as well as the calibration constants. The data that the NVRAM stores enable the 11A16 to resume Enhanced Accuracy performance (see your mainframe User Reference for Enhanced Accuracy operation) from a powered-off condition, without performing a full calibration (Enhanced Accuracy) operation. The rated lifetime of the NVRAM internal power source is ten years. If the 11A16 habitually loses Enhanced Accuracy status without a system configuration change (that is, the 11A16 remains plugged into the same slot in the same mainframe), then you may need to replace the NVRAM.

Operating Environment

To ensure proper functioning and extended operation of the 11A16, operate and store the 11A16 within the following environments:

- Operate the 11A16 in a mainframe where the ambient air temperature is between 0° and +50°C.
- Store the 11A16 in ambient temperatures from -40° to +75°C.
- After storing the 11A16 at temperatures outside the operating limits, allow the 11A16 to reach the safe operating temperature before applying power.

Enhanced system accuracy is available after a 20-minute warmup period. If the mainframe is in the Enhanced Accuracy state and the internal temperature of the mainframe changes $\pm 5^{\circ}$ C, the mainframe reverts to normal accuracy.

Packaging for Shipment

If you are shipping the 11A16 to your local Tektronix service center for repair, attach a tag to the instrument with the following information:

- Name and address of the 11A16 owner.
- Name of a person at your firm who can be contacted about the 11A16.
- 11A16 type and serial number.
- Description of the service required.

Save and reuse the original carton and packaging when shipping the 11A16 by commercial transportation. Be sure to package and ship the 11A16 and mainframe separately. If the original package is not available or is not reusable, package the 11A16 as follows:

- Obtain a corrugated cardboard cardon with dimensions at least six inches
 (15 cm) greater than the 11A16 dimensions. Use a carton with a bursting test
 strength of at least 200 pounds per square-inch.
- 2. Fully wrap the 11A16 with anti-static sheeting to protect its finish.
- 3. Tightly pack 3 inches of dunnage or urethane foam between the carton and the 11A16 to cushion it.
- 4. Seal the carton with shipping tape or with industrial staples.
- 5. Mark the address of the Tektronix service center and your return address on the carton.

Instrument Options

Your 11A16 may be equipped with one or more options. A brief description of the available options follow. For further information and prices, see your *Tektronix Product Catalog* or contact your local Tektronix service center.

Option 20 - adds two A6302 Current probes.

Checks and Adjustments

This section contains procedures that allow you to examine measurement limits and electrical specifications of the 11A16 Two-Channel Current Amplifier. Procedures 1–13 (see Table 2-1) are intended to return the 11A16 to proper operation following repair or to serve as part of a routine maintenance program.

To ensure accurate operation of the 11A16, check the electrical adjustment after each 2,000 hours of operation or every 24 months if you use the 11A16 infrequently. Refer to the 11A16 User Reference for more information about specifications and amplifier operation. If an A6303 Current probe is to be used in the following procedures, you should first calibrate it using the procedure on page 2-6.

To verify that the instrument is functioning, perform the procedures which have a "\nu" indication in the Functional Test column of Table 2-1. If you wish to verify the specifications of the instrument, perform all procedures.

Table 2-1 — Measurement Limits, Specifications, Adjustments, and Functional Test

| Procedure and Description | Measurement Limits (Examine) | Specifications (Check) | Adjustments (Adjust) | Functional Test |
|--|------------------------------------|---|-------------------------|--------------------|
| Procedure 1 Initial Setup | none | none | none | V |
| Procedure 2 Enhanced Accuracy | successful execution | none | none | V |
| Procedure 3 High Frequency Response | | | | V |
| Amplifier Step Response | aberrations ≤5% peak and 8% p-p | none | none | |
| Amplifier Bandwidth | none | amplitude at 120 MHz ≥ 78% of 500 kHz reference | none | |
| Procedure 4 Overload | none | coupling changes to off | none | V |
| Procedure 5 Input Resistance | none | 50 Ω ±2% | none | V |
| Procedure 6 DC Balance | none | refer to Table 2-4 | none | |
| | | | | |

Table 2-1 — Measurement Limits, Specifications, Adjustments, and Functional Test (Cont.)

| Procedure and Description | Measurement Limits (Examine) | Specifications (Check) | Adjustments (Adjust) | Functional Test |
|------------------------------------|---------------------------------|--|----------------------|--------------------|
| Procedure 7 Vertical Accuracy | | | | V |
| Gain | none | 5 V ±50 mV for the 11400-Series (DSA 600) | none | |
| Procedure 8 Bandwidth Limit | none | at 100 MHz limit: 2.45 ns < rise time < 4.55 ns | none | V |
| , | | at 20 MHz limit; 12.3 ns < rise time < 22.7 ns | | |
| Procedure 9 AC Coupling | none | bottom of square wave at center graticule line then waveform vertically centered on screen | none | ~ |
| Procedure 10 ΔV DC Accuracy | none | 2 mV - 2 V/div ±0.53%; 1 mV ±0.78% | none | |
| Procedure 11 DC Offset Accuracy | none | refer to Table 2-6 | none | |
| Procedure 12 Degauss Ability | none | signal trace zero | none | V |
| Procedure 13 Probe Calibration | none | successful auto- calibration | | V |

Test Equipment

Table 2-2, Test Equipment, lists recommended test equipment for use when checking and/or adjusting the amplifier. The Functional Test column of Table 2-2 indicates, with a check mark (ν), the test equipment that is recommended if you are performing a functional test only. Check and Adjustment steps are based on the test equipment examples given, but other equipment with similar specifications may be substituted. If you use different equipment, this may alter test results, setup information, and required connectors and adapters.

Table 2-2 — Test Equipment

| Description | Minimum Specification | Examples of Recommended Test Equipment | Functional Test |
|---|---|---|--------------------|
| 11400 or DSA 600 Series Mainframe that accepts amplifiers | Tektronix mainframe that accommodates amplifiers | TEKTRONIX 11401 Digitizing Oscilloscope 11402 Digitizing Oscilloscope 11403 Digitizing Oscilloscope 11403A Digitizing Oscilloscope DSA 600 Series Digitizing Signal Analyzers CSA 404 Communications Signal Analyzer | ~ |
| Current Probe | A63021 or A63032 | Tektronix A6302 ¹ with serial number above B050000 or A6303 ² probes | V |
| Leveled Sine Wave Generator | 260 kHz to 250 MHz, Leveled variable amplitude, 50 kHz ref | TEKTRONIX SG 503 Leveled Sine Wave Generator with a TM 500-Series Power Module | V |
| Power Supply | Continuously variable from 0-40 V; current limit, adjustable from 0-400 mA; 20 V at 400 mA with over current protection | TEKTRONIX PS 503A Dual Power Supply with a TM 500-Series Power Module | V |
| DC Voltage Calibrator | Output, 0-4 V; accuracy and short term stability > 0.05% | Fluke 5101B, Fluke 343A (portable) Data Precision 8200 | |
| Digital Multimeter (with test leads) | Accuracy ≤0.01% | Fluke 8842A Digital Multimeter | V |
| Calibration Generator | Period, 10 ms to 1 μs; Amplitude, fast rise mode (≤1 ns) 1 V, Standard mode 200 μVp-p to 5 Vp-p into 50 Ω; Square wave output, 0.25% accuracy, 1-2-5 amplifier selection. | TEKTRONIX PG 506A Calibration Generator with a TM 500-Series Power Module | V |
| Voltage Adapter | BNC to 12-pin current probe connector | Tektronix Part 015-0598-00 (11A16 standard accessory) | ~ |

¹A6302 Current probes with Serial Numbers greater than B050000 have nickel-plated connectors which provide better shield grounding and superior immunity to electromagnetic noise.

2-3

²A6303 Current probes should be calibrated with the procedure on page 2-6 before use in the verification procedures.

Table 2-2 — Test Equipment (Cont.)

| Description | Minimum Specification | Examples of Recommended Test Equipment | Functional Test |
|--|---|--|--------------------|
| Current Loop Adapter | Probe calibration fixture $(0 \ \Omega)$ for use with 11400 and DSA600 Series Oscilloscopes | Tektronix Part 015-0601-00 (11A16 standard accessory) | ν |
| Coaxial Cable, 36-inch (2 required) | 50 Ω , 36-inch male BNC connectors | Tektronix Part 012-0482-00 | |
| Coaxial Cable, 42-inch (2 required) | 50 Ω , 42-inch male BNC connectors | Tektronix Part 012-0057-01 | ν |
| Attenuator, 2.5X | Impedance: 50 Ω, one male and one female BNC connector | Tektronix Part 011-0076-02 | V |
| Attenuator, 5X | Impedance: 50 Ω , one male and one female BNC connector | Tektronix Part 011-0060-02 | V |
| Attenuator, 10X | Impedance: 50 Ω , one male and one female BNC connector | Tektronix Part 011-0059-02 | V |
| Adapter, BNC-to-Banana (2 required) | BNC Fernale-to-Dual Banana connector | Tektronix Part 103-0090-00 | V |
| Adapter, T | BNC, T: Two female and one male BNC connector | Tektronix Part 103-0030-00 | V |
| Adapter, BNC Barrel | BNC, Two female connectors | Tektronix Part 103-0028-00 | ν |
| Torx Screwdriver and Tips | #6 tip #8 tip #10 tip #10 tip narrow shank #15 tip | Tektronix Part 003-1415-00 Tektronix Part 003-0964-00 Tektronix Part 003-0814-00 Tektronix Part 003-0815-00 Tektronix Part 003-0966-00 | |
| Integrated Circuit Extracting Tool | IC insertion-extraction pliers, 28-pin type | General Tool P/N U505BG or equivalent | |

Using These Procedures

The first-time user should familiarize themselves with the information below prior to performing the procedures that follow.

At the beginning of each Check and Adjustment procedure, a short narrative describes the purpose of the procedure. The next section, labeled *Measurement Limit*, gives the proper range for a specification. A *Specification* section gives the result a procedure should produce. Then a *Setup to...* section provides a figure that shows test equipment setup and connection. The final section labeled *Steps Necessary To Check...* lists the steps required to check the 11A16 specification.

Conventions in this Manual

In these procedures, the following conventions are used:

- CAPITAL letters within the body of text identify front panel controls, indicators, and connectors (for example, MEASURE) on the mainframe and amplifier.
- Bold letters identify menu labels, display messages, and commands selectable from the mainframe touch panel.
- Initial Capital letters identify connectors, controls, and indicators (for example, Position) on associated test equipment. Initial Capital letters also identify adjustments inside the amplifier (for example Vert Pos).
- In some steps, the first word is italicized to identify a step that contains a performance verification and/or an adjustment instruction. For example, if Check is the first word in the title of a step, an electrical specification is checked. If Adjust appears in the title, the step involves an electrical adjustment. If Examine is the first word in the title, the step involves measurement limits that are used as calibration guides. These limits are not to be interpreted as electrical specifications.

Initial Mainframe Settings

At the beginning of most procedures, you are instructed to **Initialize** the mainframe as part of the setup. The **Initialize** feature, available through the UTILITY menu, presets all mainframe and plug-in unit controls and functions to known values. Initializing the instruments at the beginning of a step eliminates the possibility of settings from previous steps causing erroneous or confusing results. For more information on initialization, refer to your mainframe *User Reference* manual.

Menu Selections and Measurement Techniques

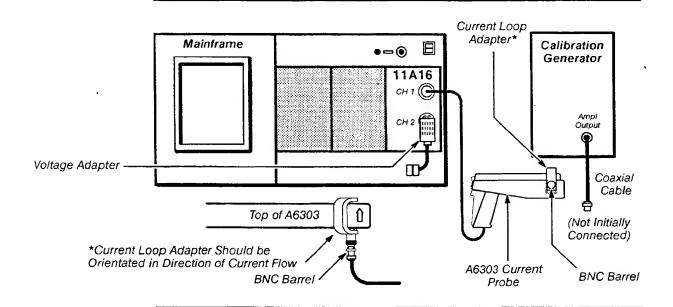
Details on measurement techniques and instructions for making menu selections are generally not included in this procedure. Comprehensive descriptions of menus and instrument features are located in your mainframe *User Reference* manual.

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A6303 Current Probe Adjustment

This procedure adjusts the A6303 for optimum operation in an 11A16 Amplifier. You should adjust an A6303 if it will be used in the following verification procedures. This procedure assumes a fully calibrated 11A16 is installed in the Right plug-in compartment of a 11400 or DSA 600 Series mainframe. The equipment required and its connection are shown in the setup illustration below.

Setup for A6303 Current Probe Adjustment



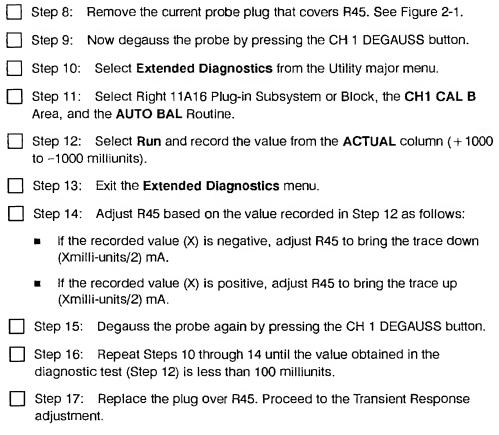
CAUTION

Use the 0 Ω Current Loop Adapter with the 11A16 Amplifier only during probe calibration. If the adapter is connected to the mainframe during power-up or Enhanced Accuracy calibration, the instrument calibration can be corrupted.

The adjustment procedure has three parts: offset adjustment, transient response adjustment, and verification.

Procedure to Adjust Offset

| • | Power up the oscilloscope mainframe, 11A16, A6303 probe and testent, and let them warm up for at least 10 minutes. |
|---------|--|
| Step 2: | Set the Calibration Generator Pulse Amplitude to Min (minimum). |
| Step 3: | Press the display CH 1 button on the 11A16 to enable the channel. |
| Step 4: | Set the Vert Size to 100 mA/div. |
| Step 5: | Set the vertical Coupling to Off. |
| Step 6: | Adjust the Vert Offset to position the trace at the graticule center. |
| Step 7: | Set Coupling back to DC. |



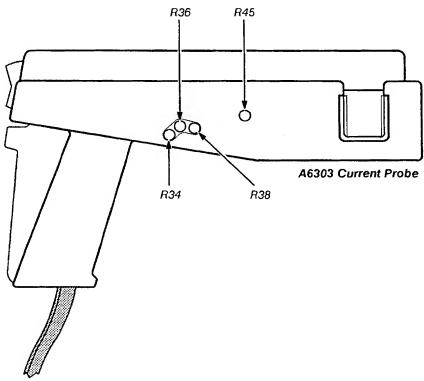


Figure 2-1 — Location of Adjustments on the A6303 Current Probe

| Pro | ceaure to | Adjust Transient Response |
|-----|--------------------------------|---|
| | CH 2 input | Connect the coaxial cable from the Calibration Generator to the through the Voltage Adapter. Leave the current probe connected to ss the display CH 2 button on the 11A16. |
| | Step 19: to DC . | Set CH 2 Vert Size to 1 V/div, Main Size to 2 ms/div, and Coupling |
| | • | Set the Calibration Generator Period to 0.1 ms and the Pulse to 5 divisions (5 V p-p). |
| | Step 21: | Press the display CH 2 button on the 11A16 to disable the channel. |
| | Step 22: | Now degauss the probe by pressing the CH 1 DEGAUSS button. |
| | • | Move the CH 2 input end of the coaxial cable to the Current Loop which should already be locked in the jaws of the A6303 probe. |
| | 15 MHz. If displayed then Aver | Set the CH 1 Vert Size to 25 mA/div and bandwidth limit to f desired, waveform Averaging may be enabled to reduce the noise. (Select Acquire Desc in the Waveform major menu, and age N and Set AvgN in the Acquire Description pop-up menu. Set ge N knob for 8.) |
| | Step 25: | Set the Calibration Generator Period to 10 ms. |
| | - | Remove the A6303 access plugs for adjustments R34, R36, and r to Figure 2-1. |
| | Step 27: | Adjust R38 for maximum flatness on the displayed signal. |
| | Step 28: | Set the Calibration Generator Period to 0.1 ms. |
| | Step 29: response | Set Main Size to 10 μ s/div and adjust R34 for optimum transient . |
| | Step 30: response | Set Main Size to 1 μ s/div and adjust R36 for optimum transient . |
| | | nts R34, R36, and R38 interact and may require readjustment for sient response with the proper gain. |
| | Step 31: | Repeat Steps 25 through 30 to optimize the transient response. |
| Pro | ocedure to | Verify Probe Gain |
| | | adjustments, you will run automated probe calibration by following in the Checks and Adjustments section. |
| | • | Calibrate channel R1 , the channel to which the current probe is d, by running Steps 1 through 8 of Procedure 13, Probe Calibration. |
| | through the | Examine that the probe calibration portion passes. Note that the portion will probably not pass due to the long signal delay time the A6303 probe. If probe gain calibration passes the probe gain is bry. If probe gain calibration failed, perform the following steps. |
| | | |

| Step 34: Examine the probe gain value with Diagnostics by selecting Extended Diagnostic from the Utility major menu. |
|--|
| Step 35: Select the Right Subsystem, the 11A16 Block, the CH1 CAL B Area and the Probe Gain Routine. |
| Step 36: Select Run and record the value shown in the ACTUAL column. The ACTUAL value should be between MIN and MAX (-15% to -5%). Values of -10% to -12% are typical. |
| Step 37: If the ACTUAL Probe Gain value is within the acceptable range, and probe gain calibration failed in Step 32, then the 11A16 should be examined by a Tektronix service center. |
| If the ACTUAL Probe Gain value is <i>less than</i> –15%, adjust R38 to increase the signal amplitude slightly and compromise step flatness. Now optimize transient response by performing Steps 18 through 30, while skipping Step R27. <i>DO NOT</i> readjust R38 in Step 27, as you have just set it to meet probe gain requirements. |
| Step 38: Ensure that Probe Gain is now correct by repeating the gain check in Steps 34 through 36. |

Procedure 1 Initial Setup

This procedure shows the setup and lists the steps necessary to configure the mainframe and 11A16. Its purpose is to warm the instruments and test equipment to the proper operating temperature. The Checks and Adjustments procedures should be performed within the ambient temperature range of $+18^{\circ}$ and $+28^{\circ}$ C, to ensure proper mainframe and 11A16 operation.

Specification

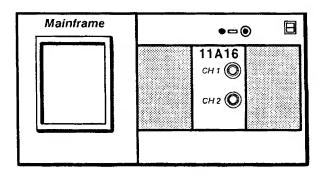
Power on and warm test equipment.

CAUTION

To avoid equipment damage, set the mainframe ON/STANDBY switch to STANDBY before installing or removing plug-ins.

Turning the mainframe power off during probe calibration, self-calibration, Extended Diagnostics, or other intense system activity may result in some internal data being corrupted. If corruption occurs, refer to Restoring Calibration Data in Section 3.

Setup for Initial Setup



Steps Necessary for Initial Setup

| Step 1: | Power on the following test equipment. |
|---------|---|
| Leveled | upply on generator sine wave generator ultimeter |
| • | With the ON/STANDBY switch set to STANDBY, connect the ne to a suitable power source. |
| Step 3: | Install the 11A16 in the Center plug-in compartment |
| Step 4: | Set the front panel ON/STANDBY switch to ON. |
| Step 5: | Allow all equipment to warm up for 20 minutes before continuing. |

Procedure 2 **Enhanced Accuracy**

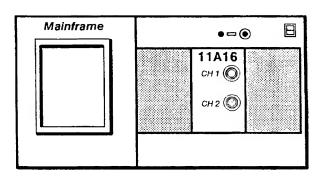
This procedure describes the setup and lists the steps necessary to check the Enhanced Accuracy state of the mainframe. Its purpose is to verify that the Enhanced Accuracy state can be achieved by the mainframe and 11A16. When the mainframe and 11A16 achieve Enhanced Accuracy, the mainframe will display the symbol (EA). The mainframe stores both the time of calibration and ambient temperature for use in maintaining the Enhanced Accuracy state.

For more information about the Enhanced Accuracy state, see Enhanced Measurement Accuracy Indicator in your mainframe User Reference manual.

Specification

When invoked, the Enhanced Accuracy self-calibration executes successfully.

Setup to Check Enhanced Accuracy



Steps Necessary to Check Enhanced Accuracy

| | Step 1: | Initialize the mainframe settings from the UTILITY major menu. |
|-------------------|---------------------------------------|---|
| | | Plug-in no setting changes ne no setting changes |
| | to achieve | Twenty minutes after power-on, the mainframe must recalibrate itselfore the Enhanced Accuracy state. Press the ENHANCED ACCURACY A prompt then appears on the display. Press the ENHANCED ACY button again. Enhanced Accuracy is achieved after several action. |
| res dia unj | ult in Iosi gnostic e predictab | mainframe power off during Enhanced Accuracy testing may ng some of the non-volatile RAM data. This could cause rrors at the next power-up, and cause the mainframe to operate ly. If this event occurs, refer to Restoring Calibration Data in |

CAUTION

ur maintrame Service Reference manual.

Step 3: Examine the display for the message, Enhanced Accuracy in Progress appears. This indicates that the mainframe is performing self-calibration to achieve Enhanced Accuracy.

| Procedure | 2 | Enhanced | Accuracy |
|-----------|---|-------------|-----------|
| riocedure | _ | EIIIIaiiceu | ALLUITALY |

| Step 4: Examine the display for an Enhanced Accuracy complete message indicating that the Enhanced Accuracy state has been achieved. The EA indicator appears on the left portion of the display when Enhanced Accuracy is active. |
|--|
| |

2-12

Procedure 3 High Frequency Response

This procedure shows the setup and lists the steps necessary to check the 11A16 high frequency response. The procedure verifies that the aberrations are not excessive and that the bandwidth with the Voltage Adapter (a standard accessory) is adequate. The procedure has two parts: Examine Amplifier Step Response and Check Amplifier Bandwidth.

To obtain lower deflection factors, attenuators are used to reduce the amplitude of the 11A16 input signal.

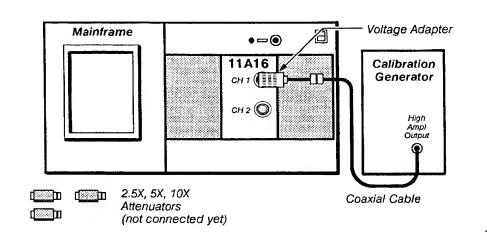
Specification (Step Response)

The system (mainframe/11A16) aberrations should not exceed 5% peak and 8% peak-to-peak.

Specification (Bandwidth)

A peak-peak measurement at 120 MHz ≥78% of the amplitude at 50 kHz.

Setup to Examine Amplifier Step Response



Steps Necessary to Examine Amplifier Step Response

| wing |
|-------|
| |
| Ampi |
| 1 μs |
| V p-p |
| |
| on |
| |
| V/div |
| s/div |
| |

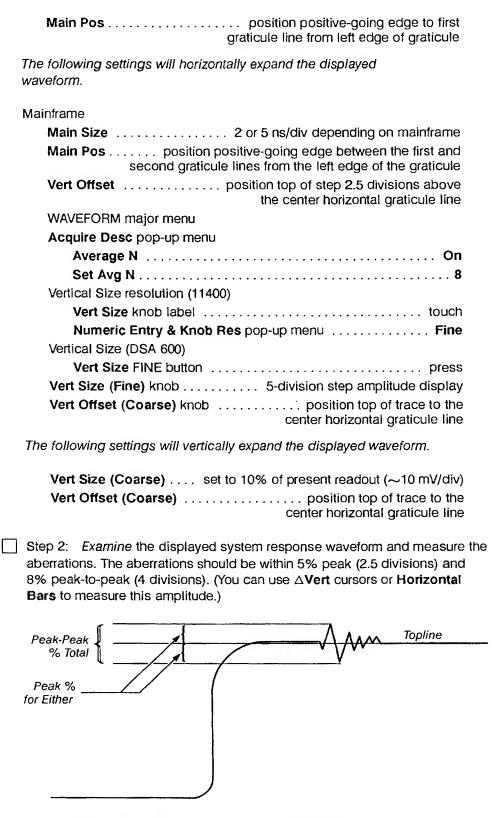


Figure 2-2 — Measurement of Plug-in Contribution to Aberrations

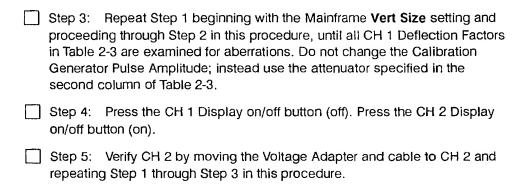


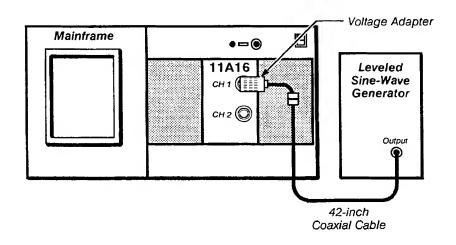
Table 2-3 — Deflection Factors and Associated Test Conditions

| Vert Size (Deflection Factor) | Attenuator Between Pulser and Adapter | Peak Amplifier Aberrations | Peak-to-Peak Amplifier Aberrations |
|-------------------------------------|---|----------------------------------|--|
| 100 mV/div | none | 5% | 8% |
| 50 mV/div | none | 4.5% | 7% |
| 20 mV/div | 2.5X | 4.5% | 7% |
| 10 mV/div | 5X | 4.5% | 7% |
| 5 mV/div | 10X | 4.5% | 7% |
| 2 mV/div | 10X + 2.5 X | 4.5% | 7% |
| 1 mV/div | 10X + 5X | 4.5% | 7% |

¹This aberration percentage does not include the mainframe aberration.

11A16 Service Reference 2-15

Setup to Check Amplifier Bandwidth



Steps Necessary to Check Amplifier Bandwidth:

The specifications for Amplifier Bandwidth are located on page 2-13.

| • | First Initialize the mainframe settings, then perform the following in the order listed: |
|--------------------|--|
| | Display on/offon |
| Freq | sine wave generator uency 500 kHz |
| Mainfran Vert | ne |
| | n Size10 μs/div uire Desc pop-up menu |
| | Average N On Set Avg N 128 |
| Step 2: | Set the leveled sine-wave generator for 3 V peak-peak (6 div). |
| amplitud | Select the Peak-Peak measurement to measure the peak-to-peak le of the waveform. Be sure the mainframe trigger is stable. Record c-Peak measurement for the reference waveform. |
| maximum combina | Set the leveled sine wave generator Frequency control to the m bandwidth frequency specified for the mainframe/11A16 ation, 120 MHz. This limit is displayed as BW Limit (WAVEFORM enu, Input Parameters pop-up menu). |
| Step 5: | Set the Main Size to 5 ns/div. |
| • | Check that the Peak-Peak measurement is at least 2.34 V (78% of k-peak amplitude measured in Step 3). |

| , roccadic o inigii i regaciiof ileoponio | Procedure | 3 High | Frequency | Response |
|---|-----------|--------|-----------|----------|
|---|-----------|--------|-----------|----------|

| | Step 7: | Set the CH 1 display on/off button to off. |
|---|---------|--|
| _ | • | Move the Voltage Adapter and coaxial cable to the CH 2 input and isplay on/off button to on. |
| | Step 9: | Perform the Steps 1 to 6 for the CH 2 input. |

11A16 Service Reference 2-17

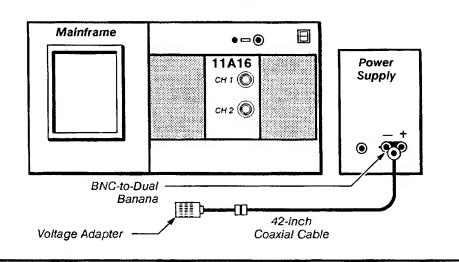
Procedure 4 Overload

This procedure shows the setup and lists the steps necessary to check the input overload response. Its purpose is to verify that the 11A16 responds properly to overload conditions by turning coupling off.

Specification

Coupling changes to Off within 2 seconds.

Setup to Check Overload



Steps Necessary to Check Overload

| • | First Initialize the mainframe settings, then perform the in the order listed: | followi | ing |
|----------|---|---------|------|
| Center P | Plug-in | | |
| CH 1 | 1 Display on/off | | on |
| Mainfran | ne | | |
| Vert | Size 5 | 50 mU/ | /div |
| Inpu | ut Parameters (DSA 600) | to | uch |
| | Coupling C1 and C2 | | DC |
| Cou | ıpling (11400) | | |
| | C1 and C2 | | DC |
| Power si | upply | | |
| Volts | s | | 4 V |
| O | en ak t innit | 400 | ^ |

CAUTION

In the following steps, **IMMEDIATELY** disconnect the cable from the input if the coupling does not change within 2 seconds.

Step 2: Ensure that CH 1 is selected by touching its waveform on the display or by pressing the CH 1 Display on/off button twice.

| Paramet | ers (DSA 600) as you connect the Voltage Adapter/coaxial cable power supply to the CH 1 input. |
|-----------------------|--|
| Step 4: | Examine that Coupling changes to Off. |
| Step 5: | Disconnect the power supply at the input. |
| Step 6: | Repeat Steps 2 through 5 for the CH 2 input. |
| Step 7: | Set the Coupling for CH1 and CH 2 to DC. |
| Step 8: | Set Vert Size to 2 U/div. |
| Step 9: | Set the power supply output to 12 V. |
| Step 10: coaxial o | Connect the power supply to the CH 1 input using the 42-inch cable. |
| Step 11: | Examine that Coupling changes to Off. |
| Step 12: | Disconnect the power supply at the input. |
| Step 13: | Set the CH 2 Display on/off to on. |
| Step 14: | Repeat Steps10 through13 for the CH 2 input. |

11A16 Service Reference 2-19

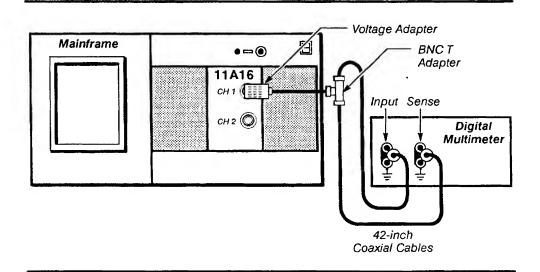
Procedure 5 Input Resistance

This procedure shows the setup and lists the steps necessary to check input resistance. Its purpose is to verify that input resistance is within the proper range.

Specification

Input resistance is 50 Ω within 1.5% (±0.75 Ω).

Setup to Check Input Resistance



Procedure to Check Input Resistance

| • | First Initialize the mainframe settings, then perform the following in the order listed: |
|----------------------|--|
| Mainfram Center P | ne no setting changes lug-in |
| | Display on/offon on the control of the contro |
| Resi | stance mode 4-Wire |
| Step 2: | Examine that CH 1 input resistance is 50 Ω within $\pm 0.75~\Omega$. |
| • | Repeat Input Resistance Check (Step 2) with the Vert Size set to div, then 50 mV/div. |
| • | Move the Voltage Adapter from CH 1 to CH 2 and repeat Steps 2 r the CH 2 input. |

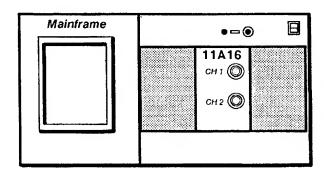
Procedure 6 DC Balance

This procedure shows the setup and lists the steps necessary to check DC balance. Its purpose is to confirm that DC balance can be accomplished accurately. The position of the displayed trace with no input signal applied is examined. This procedure must be performed immediately (5 minutes) after Enhanced Accuracy calibration.

Specification

Refer to Table 2-4.

Setup to Check DC Balance



Steps Necessary to Check DC Balance

| Step 1: First run the Enhanced Accuracy calibration (if it has not been run in over 5 minutes) by pressing the ENHANCED ACCURACY button twice in succession. Enhanced Accuracy is achieved after several minutes. |
|---|
| Step 2: Initialize the mainframe settings, then perform the following settings in the order listed: |
| Center plug-in |
| CH 1 Display on/offon |
| Mainframe |
| Vert Size 1 U/div |
| Main Pos 25.5 μs |
| WAVEFORM major menu |
| BW Limit (11400) |
| Input Parameters (DSA 600) touch |
| Bandwidth |
| Acquire Desc |
| Average N On |
| Set AvgN32 |
| MEASUREMENT major menu |
| Measurement Mean |
| Mean touch |
| Data Interval whole zone |

| • | Check that the Mean readout is within the appropriate Error Limit Table 2-4. |
|---------|--|
| Step 4: | Repeat Step 3 for each Vert Size setting in Table 2-4. |
| Step 5: | Set the CH 1 Display on/off to off. |
| Step 6: | Set the CH 2 Display on/off to on. |
| Step 7: | Repeat Steps 1 to 4 for the CH 2 input. |
| | |

Table 2-4 - 11A16 DC Balance Error Limits

11400-Series Shift

| Vert Size | (± div) | Error Limit |
|------------|---------|-------------|
| 1 U/div | 0.07 | 70 mU |
| 100 mU/div | 0.07 | 7.0 mU |
| 50 mUdiv | 0.1 | 5.2 mU |
| 20 mU/div | 0.11 | 2.2 mU |
| 10 mU/div | 0.12 | 1.2 mU |
| 5 mU/div | 0.14 | 0.7 mU |
| 2 mU/div | 0.2 | 0.4 mU |
| 1 mU/div | 0.3 | 0.3 mU |

Procedure 7 Vertical Accuracy

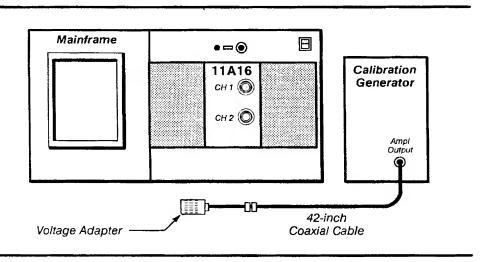
This procedure shows the setup and lists the steps necessary to check vertical accuracy. Its purpose is to verify that the accuracy of DC levels is within the proper range. The instrument must be checked immediately after Enhanced Accuracy calibration.

Specification

Measurement of $\pm 0.2\%$ Peak-Peak resolution for the 11400 Series mainframe.

Measurement of ± 0.8% Peak-Peak resolution for the DSA 600 Series mainframe.

Setup to Check Vertical Accuracy



Steps Necessary to Check Vertical Accuracy

| Step 1: First run the Enhanced Accuracy calibration by pressing the ENHANCED ACCURACY button twice in succession. Enhanced Accuracy is achieved after several minutes. | | |
|--|--|--|
| Step 2: Now Initialize the mainframe settings, then set the following parameters in the order listed: | | |
| Center Plug-in CH 1 Display on/off | | |
| Mode Std Ampl | | |
| Amplitude Output | | |
| Mainframe | | |
| Main Size | | |
| Acquire Desc | | |
| Average N (if available) On | | |
| No. Average 32 | | |
| Vert Offset 0 U | | |

11A16 Service Reference 2-23

| Coupling | |
|----------|--|
| | C1 and C2 DC |
| | Connect the Calibration Generator output to the CH 1 input using the coaxial cable and the Voltage Adapter. |
| Step 4: | Set the Vert Size to 1 V/div. |
| Step 5: | Set the Vert Offset to +2.5 V. |
| Step 6: | Select the Peak-Peak measurement (Measure major menu). |
| Step 7: | Check that the measurement is 5 V, \pm 50 mV (with averaging on). |
| | Press the CH 1 Display on/off button to turn CH 1 off. Press the CH 2 on/off button to turn CH 2 display on. |
| Step 9: | Repeat the Steps 2 through 7 for the CH 2 input. |

Procedure 8 Bandwidth Limit

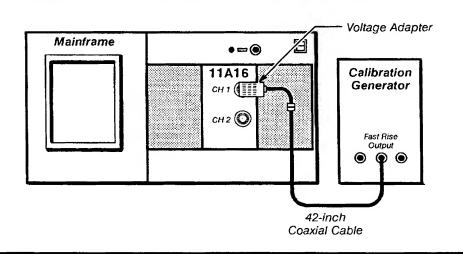
This procedure shows the setup and lists the steps necessary to check bandwidth limiting. Its purpose is to verify that rise time is within the proper range for a particular bandwidth limit filter.

Specification

At a bandwidth limit of 100 MHz, rise time is: $2.45 \, \text{ns} < > 4.55 \, \text{ns}$.

At a bandwidth limit of 20 MHz, rise time is: 12.3 ns < > 22.7 ns.

Setup to Check Bandwidth Limit



Steps Necessary to Check Bandwidth Limit

| Step 1: First Initialize the mainframe settings, then set the following parameters in the order listed: |
|--|
| Center Plug-in |
| CH 1 Display on/off on |
| Calibration generator |
| Period1 μs |
| Mode Fast Rise |
| Pulse Amplitude 5 divisions (1 V p-p) |
| Mainframe |
| Main Size 5 ns/div |
| Main Pos25.5 ns (position rising edge at screen center) |
| Vert Size |
| Vert Offset 500 mV |
| WAVEFORM major menu |
| BW Limit (11400) 100 MHz |
| Input Parameters (DSA 600) touch |
| Bandwidth |

| • | With these settings the display should have a five division ak signal. |
|---------|--|
| Step 3: | Select the Rise Time measurement (MEASURE major menu). |
| Step 4: | Check that the rise time is between 2.45 and 4.55 ns. |
| Step 5: | Set the BW Limit (11400) or Bandwidth (DSA 600) limit to 20 MHz. |
| Step 6: | Check that the rise time is between 12.3 and 22.7 ns. |
| Step 7: | Set the CH 1 Display on/off to off. |
| Step 8: | Set the CH 2 Display on/off to on. |
| Step 9: | Repeat Steps 1 through 6 for the CH 2 input. |

Procedure 9 AC Coupling

This procedure shows the setup and lists the steps necessary to check AC coupling. Its purpose is to verify that AC coupling operates accurately.

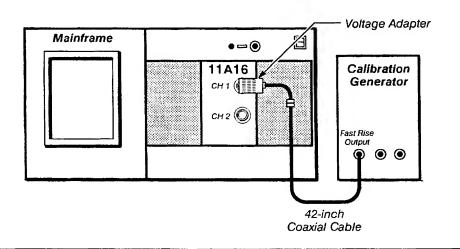
Specification

Bottom of square wave is near the center graticule line.

The waveform is vertically centered on the screen and resembles Figure 2-3.

At 1 mV/div the waveform is within 0.3 divisions of vertical center.

Setup to Check AC Coupling



Steps Necessary to Check AC Coupling

| • | First Initialize the mainframe settings, then perform the following in the order listed: |
|---|---|
| Calibration Mode Amp Perion Mainfram Vert | Display on/off on on on generator e |
| Wan | 1 3126 2 1113/div |
| - | Examine that the bottom of the square wave is near the center line as shown at the top of Figure 2-3. |
| Step 3: | Select AC Coupling for the CH 1 input. |
| • | Examine that the displayed waveform is vertically centered and that oles the bottom waveform in Figure 2-3. |

Step 5: Set the CH 1 Display on/off to off. Step 6: Move the Voltage Adapter and coaxial cable to the CH 2 input. Step 7: Set the CH 2 Display on/off to on and repeat Steps 1 through 4 for the CH 2 input. Waveform Coupling Set to DC Waveform Coupling Set to AC

Figure 2-3 — Waveform with DC Coupling (Top) and AC Coupling (Bottom)

| Step 8: | Remove the Voltage Adapter from the CH 2 input. |
|----------|--|
| Step 9: | Set CH 2 Vert Size to 1 mU/div. |
| Step 10: | Check that the trace is within 0.3 divisions of vertical center. |
| Step 11: | Set the CH 2 Display on/off to off. |
| Step 12: | Set the CH 1 Display on/off to on. |
| Step 13: | Repeat Steps 9 and 10 for CH 1. |

Procedure 10 △V DC Accuracy

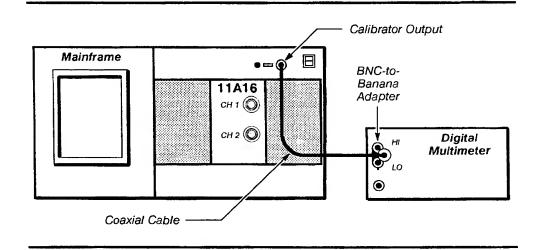
This procedure shows the setup and lists the steps necessary to check ΔV DC Accuracy. Its purpose is to confirm that the 11A16 can be accurately calibrated. Check ΔV DC Accuracy immediately after an Enhanced Accuracy calibration.

Before checking ΔV DC Accuracy you must characterize your mainframe by using the following procedure that corresponds to your mainframe series.

Specification

 ΔV DC Accuracy within $\pm 0.53\%$ from 2 mV to 2 V/div; within $\pm 0.78\%$ at 1 mV/div.

Setup to Characterize the 11400 or DSA 600 Series Mainframe

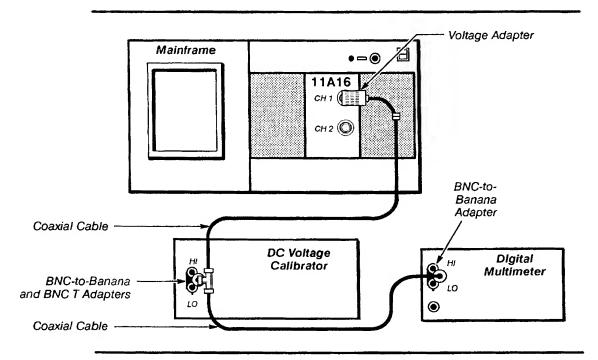


Steps Necessary to Characterize the 11400 Series Mainframe

| Step 1: Set the following parameters: | |
|---|--|
| Center plug-in no setting changes | |
| Digital multimeter (DMM) | |
| Mode DC | |
| Range Auto (Range 10 V) | |
| Mainframe | |
| UTILITY major menu Extended Diagnostics | |
| SUBSYSTEM Digitizer | |
| Block Points Acq | |
| Area FP Cal Refs | |
| Routine FP -10.000 V | |
| Run touch | |
| Step 2: Record the DMM absolute value. | |
| Step 3: Select Exit. | |
| Step 4: Select FP + 9.9951 V. | |

| | Step 5: | Select Run. |
|-----------|---------------------------------|---|
| | Step 6: | Record the DMM absolute value. |
| | Step 7: | Select Exit. |
| | Step 8: | Select Exit Diagnostics. |
| | and 6. D | Add the DMM absolute values of the readings obtained in Steps 2 ivide the result by 19.9951 V to obtain the mainframe calibration reference characterization factor. This factor is used in the "Procedure ne Amplifier". |
| Ste | ps Nece | ssary to Characterize the DSA 600 Series Mainframe |
| | Step 1: | Set the following parameters: |
| | Center plug-in | |
| | Mode DC Range Auto (Range 10 V) | |
| Mainframe | | ne LITY major menu |
| | Fred | quency |
| | Step 2: | Record the DMM absolute value. |
| | Step 3: | Adjust Amplitude to +9.9951V. |
| | Step 4: | Record the DMM absolute value. |
| | and 4. E | Add the DMM absolute values of the readings obtained in Steps 2 Divide the result by 19.9951 V to obtain the mainframe calibration reference characterization factor. |

Setup to Check the 11A16 △V DC Accuracy



Steps Necessary to Check the 11A16 $\triangle V$ DC Accuracy

| Step 1: First Initialize the mainframe settings, then perform the following settings in the order listed: |
|--|
| Center plug-in |
| CH 1 Display on/offon |
| Mainframe |
| WAVEFORM major menu |
| BW Limit (11400) |
| Input Parameters (DSA 600) touch |
| Bandwidth |
| Acquire Desc pop-up menu |
| Average N On |
| DC Voltage Calibrator |
| On/Standby |
| 50 Ω Override |

If the environment is electrically noisy, connect a capacitor (at least 0.1 $\mu\text{F})$ across the input terminals of the DC Voltage Calibrator.

Step 2: Press the Enhanced Accuracy button twice to initiate Enhanced Accuracy calibration and ensure peak performance of the system.

Immediately after self-calibration has completed and passed, perform this procedure for each channel.

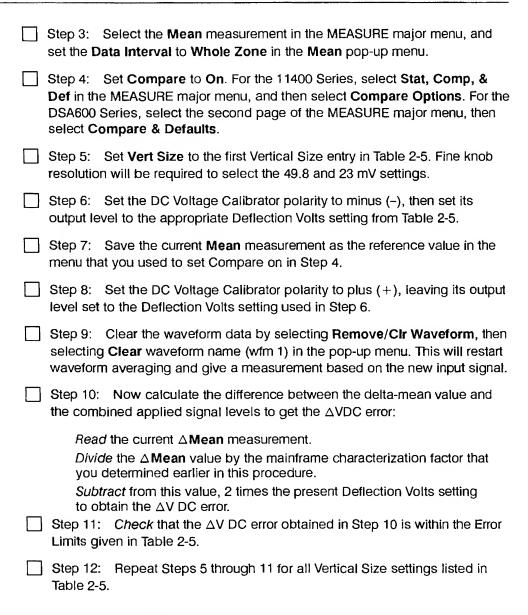


Table 2-5 — 11A16 DC Accuracy Error Limits

| Vertical Size | Deflection Volts | Error Limits (±V) |
|------------------------|-------------------------|-------------------|
| 1 V/div | 4 V | 42.4 mV |
| 100 mV/div | 400 mV | 42.4 mV |
| 50 mV/div | 200 mV | 1.06 mV |
| 49.8 mV/div (Fine res) | 200 mV | 1.06 mV |
| 23 mV/div (Fine res) | 92 mV | .98 mV |
| 20 mV/div | 80 mV | .85 mV |
| 10 mV/div | 40 mV | .42 mV |
| 5 mV/div | 20 mV | .21 mV |
| 2 mV/div | 8 mV | .085 mV |
| 1 mV/div | 4 mV | .062 mV |

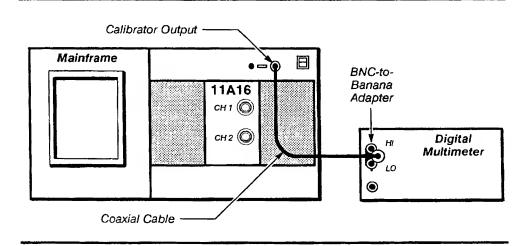
Procedure 11 DC Offset Accuracy

This procedure shows the setup and lists the steps necessary to check DC Offset. Its purpose is to confirm that the amplifier can be accurately calibrated. This procedure does not test the mainframe calibration voltage reference accuracy or long term stability. Therefore, before checking DC Offset Accuracy you must characterize your mainframe by using the procedure corresponding to your series of mainframe. Check DC Offset Accuracy immediately after an Enhanced Accuracy calibration.

Specification

Refer to Table 2-6.

Setup to Characterize the 11400 or DSA 600 Series Mainframe



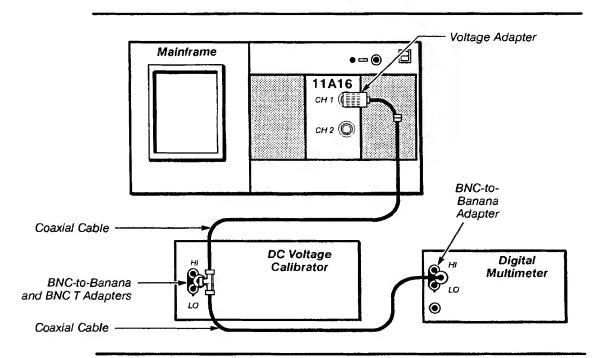
Steps Necessary to Characterize the 11400 Series Mainframe

This characterization procedure is identical to that performed in Procedure 10. You can use the mainframe calibration voltage reference characterization factor computed in Procedure 10 for the verification portion of this procedure.

| Step 1: Set the following parameters: |
|--|
| Center plug-in no setting changes |
| Digital multimeter (DMM) |
| Mode DC |
| Range Auto |
| Mainframe |
| UTILITY major menu Extended Diagnostic |
| SUBSYSTEM Digitizer |
| Block Points Acq |
| Area FP Cal Refs |
| Routine FP -10.000 V |
| Run touch |

| Step 2: | Record the DMM absolute value. |
|----------------------|---|
| Step 3: | Press Exit. |
| Step 4: | Press FP +9.9951 V . |
| Step 5: | Press Run. |
| Step 6: | Record the DMM reading. |
| Step 7: | Press Exit. |
| Step 8: | Press Exit Diagnostics. |
| and 6. D voltage | Add the absolute values of the DMM readings obtained in Steps 2 divide the result by 19.9951 V to obtain the mainframe's calibration reference characterization factor (which is used in the Procedure to Amplifier). |
| Steps Nece | ssary to Characterize the DSA 600 Series Mainframe |
| Step 1: | Set the following parameters: |
| Center p Mainfrar | olug-in no setting changes |
| UTII | LITY major menu |
| | quency DC |
| • | ust Amplitude |
| | de DC |
| Ran | nge Auto |
| Step 2: | Record the DMM absolute value. |
| Step 3: | |
| L Otop o. | Adjust Amplitude to +9.9951V. |
| | Adjust Amplitude to +9.9951V. Record the DMM reading. |

Setup to Check the 11A16 DC Offset Accuracy



Steps Necessary to Check the 11A16 DC Offset Accuracy

across the input terminals of the DC Voltage Calibrator.

- Step 2: Press the Enhanced Accuracy button twice. Immediately after self-calibration has completed and passed, perform this procedure for each channel.
- Step 3: Select the **Mean** measurement in the MEASURE major menu, and set the **Data Interval** to **Whole Zone** in the **Mean** pop-up menu.

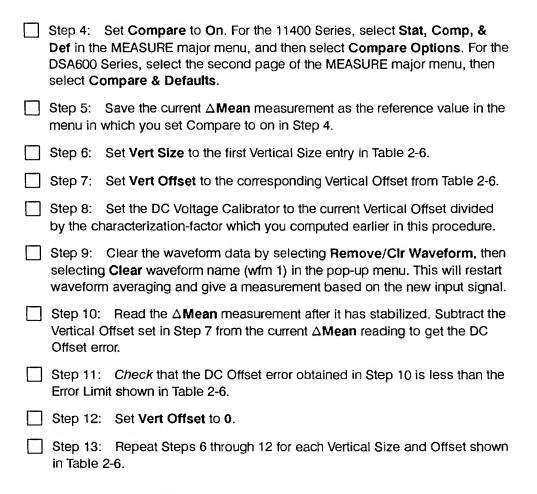


Table 2-6 — 11A16 DC Offset Accuracy

| Vertical Size | Vertical Offset | Error Limit (±Volts) |
|---------------|-----------------|----------------------|
| 1 V/div | 4 V | 50 mV |
| 0.1 V/div | 4 V | 14 mV |
| 1 mV/div | 1 V | 2.4 mV |
| 1 mV/div | 800 mV | 2.0 mV |
| 1 mV/div | 600 mV | 1.6 mV |
| 1 mV/div | 400 mV | 1.2 mV |
| 1 mV/div | 200 mV | 0.8 mV |

Procedure 12 Degauss Ability

This procedure shows the setup and lists the steps necessary to check probe degauss ability. Its purpose is to confirm that the 11A16 can degauss its current probe and zero its output signal. This procedure will verify that the front-end 11A16 circuitry such as the Power Amplifier, Hall Effect Amplifier, and the degauss Signal Generator are operating properly. Check degauss ability immediately after an Enhanced Accuracy calibration.

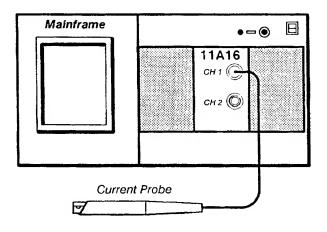
Specification

The mainframe zeros the displayed waveform to the horizontal center line within:

 $A6302 - 0.25 \, \text{mA} + 0.1 \, \text{div}$

A6303 - 1.0 mA + 0.1 div

Setup to Check the 11A16 degauss Ability



Steps Necessary to Check degauss Ability

| ENHANCED ACCURACY button twice in succession. Enhanced Accuracy is achieved after several minutes. |
|--|
| Step 2: Initialize the mainframe settings, then perform the following settings in the order listed: |
| Center plug-in CH 1 Display on/off |
| Input Parameters (DSA 600) touch |
| Coupling C1 and C2 DC |
| Coupling (11400) |
| Vert Size |
| Main Size 5 ms/div |

| Acq | uire Desc pop-up menu |
|---------|--|
| | Average N On |
| : | Set Avg N |
| Step 3: | Ensure that the jaws are closed, then press the DEGAUSS button. |
| Step 4: | Examine that the message DAC Overflow is not displayed. |
| Step 5: | Set Coupling to OFF. |
| Step 6: | Adjust Vert Offset so that the trace is on the center graticule. |
| Step 7: | Set Coupling to DC. |
| Step 8: | Press the DEGAUSS button. |
| · . | Check that the signal trace is vertically zeroed to the center graticule e specifications given above. |
| | Check CH 2 by moving the current probe to CH 2 and repeating through 9. |

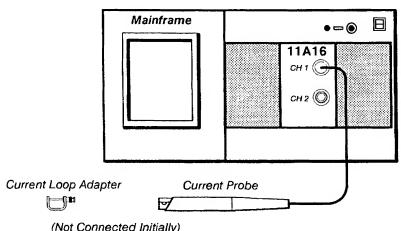
Procedure 13 **Probe Calibration**

This procedure shows the setup and lists the steps necessary to check probe calibration. Its purpose is to confirm that the mainframe and 11A16 can calibrate the current probe using the Current Loop adapter connected to the mainframe Calibrator BNC output. DO NOT connect the Current Loop adapter at this time. This procedure will further verify that the front-end 11A16 circuitry such as the Power Amplifier, Hall Effect Amplifier, and the Attenuators are operating properly.

Specification

The mainframe calibrates the current probe without a failure.

Setup to Check the 11A16 Probe Calibration



(Not Connected Initially)

Steps Necessary to Check Probe Calibration

Step 1: If the EA (Enhanced Accuracy) icon is not displayed, then press the ENHANCED ACCURACY button twice in succession.



Enhanced Accuracy should NOT be invoked when the Current Loop Adapter is connected to the calibrator output of the mainframe. The Current Loop Adapter places a considerable load on the precision voltage reference in the mainframe. During an Enhanced Accuracy calibration, the precision reference can be overloaded resulting in a calibration error.

Ensure that Enhanced Accuracy is in Manual mode by checking the Instrument Modes or Modes pop-up menu of the Utility 1 major menu. Errors can occur if Enhanced Accuracy is automatically invoked during probe calibration.

| į . | Step 2: | Initialize | the mainframe | settings in | the Utility | y menu. |
|-----|---------|------------|---------------|-------------|-------------|---------|
|-----|---------|------------|---------------|-------------|-------------|---------|

Step 3: Press the CH 1 display On/Off button to display CH 1.

| Step 4: Press the DEGAUSS button. Let the probe warm up for 10 minutes. |
|--|
| Step 5: Install the Current Loop Adapter on the mainframe CALIBRATOR output BNC. Attach the current probe head to the test bar of the Current Loop Adapter. |
| The arrow on the probe indicates the direction of positive "current" flow. The arrow must be pointing away from the mainframe. |
| Step 6: Select the Probes pop-up menu in the Utility 1 major menu. |
| Step 7: Select the probe channel in the Calibrate , Deskew , and Compensate Probes section of the Probes pop-up menu located in the UTILITY major menu. For example, C1 for center plug-in compartment, CH 1. |
| If the polarity of the probe is incorrect or if the probe is not properly connected, the following warning message is displayed during the calibration: |
| Connect Probe to Calibrator and Restart Operation |
| Correct this problem by reversing the current probe connection and restarting calibration. |
| Step 8: Examine that one of the following messages is displayed after probe calibration and deskewing complete: |
| Probe Cal Complete; Deskew Passed (A6302) or, |
| Probe Cal Complete; Deskew Failed (A6303) |
| NOTE: If you are using an A6303 probe or an A6302 with a cable longer than 2 meters, the Deskew portion will likely fail due to the long time delay through the probes. The failure is due to the 15 ns deskew limit of the mainframe and is acceptable. |
| Ignore the Compensation message, since no compensation is required for a current probe. |
| Step 9: Move the current probe to CH 2 and repeat Steps 2 through 7 for the CH 2 probe. |
| Step 10: To complete the procedure, remove the Current Loop Adapter and exit the Probes pop-up menu by selecting Exit Comp . |
| If Enhanced Accuracy is invoked when the Current Loop Adapter is attached, calibration can be corrupted. |
| |

Maintenance

This section provides you with preventive maintenance, ordering information, sensitive component information, techniques to remove/replace the FRUs, and troubleshooting of the 11A16. Corrective Maintenance is limited to the replacement of FRUs or modules. Service beyond this level must be done by your Tektronix service center.

Preventive Maintenance

Preventive maintenance can prevent the 11A16 from failing and increase its reliability. Cleaning and visual inspection is all that is required for preventive maintenance. To clean or inspect the internal boards of the 11A16 you must remove its side shields.

11A16 Side Shield Removal

The side shields, top and bottom frames, and front panel reduce radiation of electromagnetic interference (EMI) from the 11A16. They also reduce the amount of dust reaching the interior. Therefore, when you are not maintaining the 11A16, keep the side shields in place.

| N-C-C | h me sign | e silieius ili piace. |
|-------|-------------------|--|
| Rer | nove a si | de shield as follows: |
| | Step 1: | Pry the side shield from the rear of the 11A16. |
| | Step 2: | Lift up on the shield. |
| | Step 3: panel. | Gently remove the shield from the grooves in the frame and front |
| Inst | all a side | shield as follows: |
| | Step 1: | Position the shield over the frame grooves. |
| | Step 2: | Slide the front lip of the side shield under the front panel. |
| | • | Press down on the shield until it snaps into place. (Pressure must ed along the full length of the frames to secure the shield.) |
| | | e 11A16 will not slide into the mainframe if the side shields are not in the frames. |
| Cle | eaning | |



Use anti-static protection to prevent static damage to components.

The 11A16 should be cleaned as often as operating conditions require. Dirt on a component acts as an insulating blanket and prevents efficient heat dissipation. Dirt also provides an electrical conduction path, which may cause the 11A16 to fail.

Exterior – dust can be removed with a soft cloth or small brush. A brush is particularly useful for dislodging dirt in and around the front panel switches. Remove the side shields before cleaning.

Interior – cleaning of the 11A16 is seldom required. If the interior of the 11A16 accumulates dust or dirt, clean with dry, low-velocity air. Remove stubborn dirt with a soft brush or a cloth dampened with a mild detergent and water solution. (A cotton-tipped applicator is useful for cleaning in narrow spaces or for cleaning delicate components.) Finally, remove any cleaning residue by wiping with a damp washcloth.

CAUTION

To prevent damage from electrical shorts, the boards and components must be dry before applying power.

Visual Inspection

The 11A16 should be inspected occasionally for loosely-seated or heat-damaged components. The corrective procedure for most visible defects is replacement of the part. Particular care must be taken if heat-damaged parts are found, since overheating usually indicates other problems.

Diagnostic Troubleshooting

The mainframe automatically performs a series of diagnostic tests when it is powered on and the microprocessor unit (MPU) is reset. The first set of diagnostic tests are the Kernel Tests which determine if the 11A16 kernel systems are operating properly. If these are successful, then the Self Tests are executed to verify the functionality of the 11A16 subsystems. Any failure causes the mainframe to enter Extended Diagnostics and to display the error index code(s) in a diagnostic menu.

The Kernel tests, Self-Tests, and Extended Diagnostics produce and format error index codes differently, so these error index codes are discussed separately.

Kernel Tests

Kernel Tests are done each time the front-panel ON/STANDBY switch is set to ON. The mainframe and 11A16 perform Kernel Tests on their microprocessor subsystems and Self Test Diagnostics on all major circuits.



Turning the mainframe power off during the execution of the diagnostic tests may result in losing some or all of the non volatile RAM (NVRAM) data (for example, calibration constants). This loss of data may cause the mainframe to operate unpredictably. If this occurs, refer to Restoring Calibration Data later in this section.

If any of the kernel tests fail, then it is unlikely that the 11A16 can communicate failure information to the mainframe. The flashing of a fault code on the front panel CH 1 and CH 2 LEDs indicates which kernel test is failing.

The following description explains how to read the fault code:

- If the 11A16 Kernel tests detect a fault, then the CH 2 LED is flashed eight times.
- If the CH 1 LED is flashed during a cycle of the CH 2 LED, then the test corresponding to the current count is the one that failed. Refer to the timing diagram in Figure 3-1 for an example LED fault code. The timing diagram illustrates a test number 2 failure.

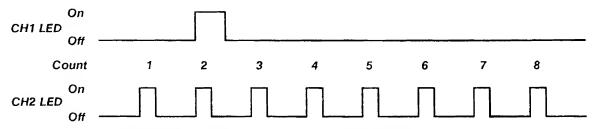


Figure 3-1 — Sample LED Fault Code Timing Diagram

The three kernel tests are:

- Test 1: The EPROM Checksum test—computes a checksum of the content of the firmware EPROM. This calculated checksum is then compared with a checksum stored in the EPROM. If the checksums do not match, the test fails, and fault code 1 is reported. After the front panel LEDs flash to report the fault code, the 11A16 attempts to begin normal operation however it is unlikely that the 11A16 can function properly with a bad EPROM Checksum.
- Test 2: The Nonvolatile RAM (NVRAM) test—verifies that the NVRAM is functioning properly. Since the NVRAM contains calibration information which must remain undamaged, this test does not alter critical data. If the testing algorithm detects a failure, then the 11A16 reports a fault code of 2 and repeatedly loops the NVRAM test. The 11A16 continues looping the NVRAM test until the mainframe is powered off (ON/STANDBY switch is set to STANDBY). Until the condition causing the NVRAM test to fail is corrected, the mainframe does not recognize the 11A16.

The NVRAM test could corrupt data stored in the NVRAM if the mainframe is powered off and on during this test. If corruption occurs, then the Calconstant Checksum is also corrupted. At the next power-on, the 11A16 resets the calibration constants to default EPROM settings and reports a plug-in (11A16) Calconstant Checksum Error during normal power-on diagnostics. To properly calibrate the mainframe and 11A16, you must initiate an Enhanced Accuracy calibration.

■ Test 3: The Housekeeper IC test—verifies the functionality of the Housekeeper IC (also referred to as the SDI IC). The Housekeeper IC performs the following housekeeping chores of the 11A16: channel sequencing, refreshing the analog control voltage system (AVCS), and providing serial data communications with the mainframe. This test exercises the IC, and records the ICs signature. If the resulting signature of the Housekeeper IC does not match a known good signature, then this test fails

and the 11A16 reports a fault code of 3 and repeatedly loops on the Housekeeper IC test.

After all kernel tests have been completed and successfully passed, the 11A16 initializes its settings and communicates with the mainframe.

Self Tests

After passing the kernel tests the mainframe requests that the 11A16 execute its Self Test routines (unless the mainframe Self Tests are disabled). If the mainframe returns to normal operation or enters into a new configuration calibration, this indicates successful completion of the Self Tests.

Self Tests diagnostics verify the following:

- Probe coding
- Calibration (cal) constant checksums
- Calibration (cal) constant values
- Analog-to-digital (ADC) and digital-to-analog (DAC) converters
- ±15 V power fuses
- Input signal path

Extended Diagnostics

After all Self Tests and Extended Diagnostics are executed, any resultant error index codes appear on the display next to the associated circuit block names in the Extended Diagnostics mainframe menu. Each circuit block that experiences failure will indicate the first error encountered and the number of failures in the Block. To get a more complete list of the error index codes in a Block, select a failed Block and then the Area selector. To display the lowest level test routines in the selected Area, select the Routine. The currently selected Block, Area, and Routine are shown.

Several diagnostic operating mode selectors are available on the screen. Refer to your mainframe *User Reference* for more information on Extended Diagnostics and Extended Test menus and operation.

Enhanced Accuracy Errors

Enhanced Accuracy Errors specify faulty FRUs that are preventing the mainframe from entering its Enhanced Accuracy state. See your mainframe *User Reference* for more information about Enhanced Accuracy.

Error Index Codes

Error Index Codes are five digit codes whose first character indicates the subsystem or 11A16 tested. The last four digits are hexadecimal (hex) numbers that indicate the Block, Area, Routine and failure identity. For example, R1241 is decoded as follows:

- R Right plug-in (facing the mainframe front panel)
- 1 Block name plug-in
- 2 Area name Group I
- 4 Routine name Checksum Probe
- 1 Failure Identity specific failure mode

The first character of an error index code indicates the compartment in which the 11A16 is installed:

- L Left
- C Center
- R Right

The tables in this section, list the four-digit failure code only; the prefix L, C, or R is omitted.

Front-panel controls are active during the Self-Test sequence and any disturbance could cause a test failure.

Error index codes are divided into three tables: Kernel test error codes (Table 3-1), Self-Tests/Extended Diagnostic error indexes (Table 3-2), and Enhanced Accuracy error indexes (Table 3-4). Each table lists suspect FRUs in the order of highest to lowest probability. For FRU identification and replacement information, refer to page 3-11.

Table 3-1 lists the error codes that result from the Kernel Tests.

Table 3-1 - 11A16 Kernel Error Index Codes

| Error Code | Suspect Module, Hybrid, or IC FRU(s) | Suspect Board |
|------------|---|---------------|
| 1 | EPROM, MPU | Main |
| 2 | NVRAM | Main |
| 3 | SDI, MPU | Main |

Table 3-2 lists the error codes that result from the Self-Tests and Extended Diagnostics.

Table 3-2 — Self-Tests/Extended Diagnostics Error Index Codes

| Error Code | Suspect Module, Hybrid, or IC FRU(s) | Suspect Board |
|-------------------|--|---------------|
| 1111 | | Main |
| 1121 ¹ | NVRAM | Main |
| 1131 ¹ | NVRAM | Main |
| 1211 | | Main |
| 1221 | FUSE | Main |
| 1311 | SDI, SMPLHD1 ² , SMPLHD2 ² | Main |
| 1811 | | Main |
| 1821 | | Main |
| 1831 | Amp | Main |
| 1841 | Amp | Main |
| 1851 | Amp | Main |
| 1861 | Amp | Main |
| 1871 | | Main |
| 1881 | | Main |
| 1891 | | Main |
| 18A1 | | Main |

When the NVRAM is replaced a new User Identification (UID) must be entered before this error can be cleared. See Programming the Unit Identification page 3-35.

Decoding an SMPLHD Failure—The Actual data accompanying an X1311 error code can be decoded to identify the suspect Sample and Hold board. The Actual data is a hexadecimal (hex) number. Convert this hex number to binary, then determine which bits are 1. Table 3-3 shows the suspect board and the board pin number for the failed ACVS channel. Refer to Figure 3-2 to locate a failed SMPLHD board.

The hex data code 0040 is equivalent to the binary 0000 0000 0100 0000. The single 1 is in Binary Bit position 6 which points to the SMPLHD2 board.

If both SMPLHD boards have failures this would point to the SDI IC or other common circuitry.

²The specific SMPLHD failure is determined by decoding the Actual data produced by the diagnostic test. Decoding is discussed below.lf both SMPLHD boards have failures, the SDI is suspect.

Table 3-3 — Sample and Hold Board Failure Codes

| Binary Bit | Suspect SMPLHD FRU | Board Pin # |
|------------|--------------------|-------------|
| 15 | SMPLHD2 | 20 |
| 14 | SMPLHD2 | 22 |
| 13 | SMPLHD1 | 20 |
| 12 | SMPLHD1 | 22 |
| 11 | SMPLHD2 | 19 |
| 10 | SMPLHD2 | 23 |
| 9 | SMPLHD1 | 19 |
| 8 | SMPLHD1 | 23 |
| 7 | SMPLHD2 | 17 |
| 6 | SMPLHD2 | 14 |
| 5 | SMPLHD1 | 17 |
| 4 | SMPLHD1 | 14 |
| 3 | SMPLHD2 | 15 |
| 2 | SMPLHD2 | 16 |
| 1 | SMPLHD1 | 15 |
| 0 | SMPLHD1 | 16 |

Table 3-4 lists the error codes that result from the Enhanced Accuracy tests. (Enhanced Accuracy is available after the system has a 20-minute warmup period.)

Table 3-4 — Enhanced Accuracy Error Index Codes

| Error Code | Suspect Module, Hybrid, or IC FRU(s) | Suspect Board |
|------------|---|---------------|
| 1411 | ATTN1 | Main |
| 1421 | AMP | Main |
| 1431 | AMP | Main . |
| 1441 | AMP . | Main |
| 1451 | AMP | Main |
| 1461 | AMP | Main |
| 1471 | AMP | Main |
| 1481 | AMP | Main |
| 1491 | AMP | Main |
| 1511 | PROBE | |
| 1521 | PROBE | |
| 1531 | | Main |
| 1541 | | Main |
| 1551 | | Main |
| 1611 | ATTN2 | Main |
| 1621 | AMP | Main |
| 1631 | AMP | Main |
| 1641 | AMP | Main |
| 1651 | AMP | Main |
| 1661 | AMP | Main |
| 1671 | AMP | Main |
| 1681 | AMP | Main |
| 1691 | AMP | Main |
| 1711 | Probe | |
| 1721 | Probe | |
| 1731 | | Main |
| 1741 | | Main |
| 1751 | | Main |

3-8

Other Messages

Other messages can be displayed by the mainframe. These are described below.

Calibrating a New Configuration

When a plug-in unit is first installed in a mainframe or when it is moved to a different compartment, the mainframe enters the new configuration mode. After power-on diagnostics, it will recalibrate itself for the new configuration. During calibration, the screen displays the message **Powerup new configuration partial calibration occurring**. If calibration is successful, the screen displays a completion message, and the mainframe begins normal operation.

Restoring Calibration Data

If the mainframe is powered off during probe calibration, Self Tests, Extended Diagnostics, or other system calibration or evaluation activity, internal NVRAM data can be corrupted. If the **Extended Diagnostic** menu is displayed after power on, then this corruption might be the cause of the apparent failure.

| | led Diagnostics menu displays a Cksm Probe error, use the ocedure to restore normal operation: |
|----------------|---|
| Step 1: | Recalibrate the probes. |
| Step 2: | Execute the Self Tests and confirm that the tests pass. |
| | led Diagnostics menu again displays a Cksm Probe error or any en use the following procedure to restore normal operation: |
| Step 3: | Exit the Extended Diagnostic menu. |
| Step 4: | Wait for self calibration to complete and pass. |
| Step 5: | Execute the Self Tests and confirm that these tests pass. |
| If this proced | dure does not restore normal operation, the 11A16 requires repair. |

Conventional Troubleshooting

This section lists faulty FRUs and symptoms that power-on diagnostics can not detect. After determining the suspect FRU, refer to Table 3-8 to locate the appropriate technique(s) to replace it.

Front Panel Connector Troubleshooting

A faulty Front Panel Connector/Cable assembly could cause a communication loss between the Front Panel board and the Main board.

Fuse Troubleshooting

To find a defective fuse, remove the 11A16 from the mainframe, and use a digital multimeter to check for continuity across each fuse. Figure 3-2 shows fuse locations. Fuses are checked by a diagnostic test.

Darlington NPN or PNP Power Transistor Troubleshooting

When using a current probe, a faulty Darlington NPN (NPNTRAN) or PNP (PNPTRAN) Power Transistor could prevent input signal amplification. Use a digital multimeter to check for at least 2–3 K Ω resistance between the emitter and collector (the two outer leads of each transistor). Additionally, the heatsink tab is the collector and the square board pad is the emitter. A blown fuse will have little affect on this measurement.

Probe Connector Troubleshooting

A faulty probe connector assembly (PCON) could cause an intermittent or complete loss of input signal. Check the continuity of each wire.

Relay Troubleshooting

The 11A16 has four relays, K1-K4, located on each Attenuator board. See Figure 3-3 for relay locations. A faulty relay could disable the following 11A16 functions for a signal channel:

- AC/DC switching, K4.
- Channel Coupling ON/OFF, K1.
- Attenuation range, (X10) K2.
- Attenuation range, (X100) K2 & K3.

Jumper Troubleshooting

The misplacement of pin jumpers could cause unpredictable operation of the 11A16.

Field Replaceable Unit (FRU) Guide

This section lists abbreviations of board FRUs, component/module FRUs, and error index codes. The error index code tables list the hybrid, integrated circuit (IC), module, or board FRU(s) suspected of causing each error. The FRU(s) in each category are listed in most-to-least probable cause (assuming only one error is indicated). If any errors occur, inspect the suspect FRU for loose connections and components and then repeat the diagnostic test. If any errors recur, then replace the suspect FRU(s) with a good FRU(s). Verify that the new FRU is a correct replacement for the old FRU. If the old FRU contains firmware, be sure that the new firmware version is either the same or updated.

Abbreviations of FRU Names

Table 3-5, Board FRUs, lists the abbreviation used in the Suspect Board FRU(s) column of Tables 3-1, 3-2, and 3-4.

Table 3-5 — Board FRUs

| Abbreviation | Name | Designator |
|--------------|----------------------|------------|
| Main | Main board | A1 |
| ATTN1 & 2 | Attenuator boards | A1A3, A1A4 |
| SMPLHD1 & 2 | Sample & Hold boards | A1A1, A1A2 |
| FPB | Front Panel boards | A2, A3 |

Abbreviations of Component Names

Table 3-6, Component/Module FRUs, lists the abbreviation used in the Suspect Module, Hybrid, or IC FRU(s) column of Tables 3-1, 3-2, and 3-4.

Table 3-6 — Component/Module FRUs

| Abbreviation | Name | Designator |
|--------------|--|------------|
| AMP1 | Tek M377 Vertical Amplifier, CH 1 | U220 |
| AMP2 | Tek M377 Vertical Amplifier, CH 2 | U260 |
| ATTN1 | Attenuator, channel 1 | J310 |
| ATTN2 | Attenuator, channel 2 | J380 |
| EPROM | Firmware | U1080 |
| FPB | Front Panel board (identical units) | A2, A3 |
| FRPAN | Front Panel | _ |
| FUSE | ± 15 V power Amp fuses (3/4 Amp) | F500, F610 |
| HTSNK | Heat Sink | - |
| HYP | Hypcon Assembly | |

Table 3-6 — Component/Module FRUs (Cont.)

| Abbreviation | Name | Designator |
|--------------|----------------------------------|----------------|
| JMPERS | Jumpers | _ |
| NPNTRAN | Darlington NPN Power Transistors | Q600, Q690 |
| NVRAM | Memory | U1000 |
| PCON | Probe Connector assembly | J1001, J1002 |
| PNPTRAN | Darlington PNP Power Transistors | Q601, Q691 |
| PROBE | A6302 or A6303 Current Probe | _ |
| RELAY | Attenuator board relays | K1, K2, K3, K4 |
| SDI | Tek M382A Serial Data Interface | U 8 50 |
| SMPLHD1 | Sample and Hold board, CH 1 | J640 |
| SMPLHD2 | Sample and Hold board, CH 2 | J650 |

Ordering Parts

If you find that it is necessary to replace a FRU or a FRU IC, it can be ordered from a Tektronix service center. When ordering replacement parts, include the following information:

- plug-in type
- plug-in serial number
- Description of the part (if electrical, include the circuit number)
- Tektronix part number

If a part you order has been replaced with a different or improved part, your local Tektronix service center or representative will contact you concerning any changes.

Static-Sensitive Device Classification



Static discharge can damage any semiconductor in the 11A16.

The 11A16 contains electrical components that are susceptible to damage from static discharge. Refer to Table 3-7, Relative Susceptibility to Damage from Static Discharge, for the relative susceptibility of various classes of semiconductors. Static voltages of 1 kV to 30 kV are common in unprotected environments.

Observe the following precautions to avoid damage:

- Minimize handling of static-sensitive components.
- Transport and store static-sensitive components or assemblies in their original containers, either on a metal surface or conductive foam. Label any package that contains static-sensitive assemblies or components.

- Wear a wrist strap while handling these components to discharge the static voltage from your body. Servicing static-sensitive assemblies or components should be performed only at a static-free work station. The use of the static control mat is recommended.
- Clear anything from the work station surface that is capable of generating or holding static charge.
- Keep component leads shorted together with conductive foam.
- Pick up components by the body, never by the leads.
- Do not slide components over any surface.
- Avoid handling components in areas that have a floor or a work-surface that is capable of generating static charge.

 Table 3-7 — Relative Susceptibility to Damage from Static Discharge

| Semiconductor Classes | Relative Susceptibility Levels ¹ |
|--|---|
| MOS or CMOS microcircuits, and discrete or linear microcircuits with MOS inputs (most sensitive) | 1 |
| ECL | 2 |
| Schottky signal diodes | 3 |
| Schottky TTL | 4 |
| High-frequency bipolar transistors | 5 |
| JFETs | 6 |
| Linear microcircuits | 7 |
| Low-power Schottky TTL | 8 |
| TTL (least sensitive) | 9 . |

¹Voltage equivalent for levels.

1 = 100 to 500 V 2 = 200 to 500 V 3 = 350 V 6 = 600 to 800 V 7 = 400 to 1000 V (est.)

3 = 250 V 8 = 900 V 4 = 500 V 9 = 1200 V

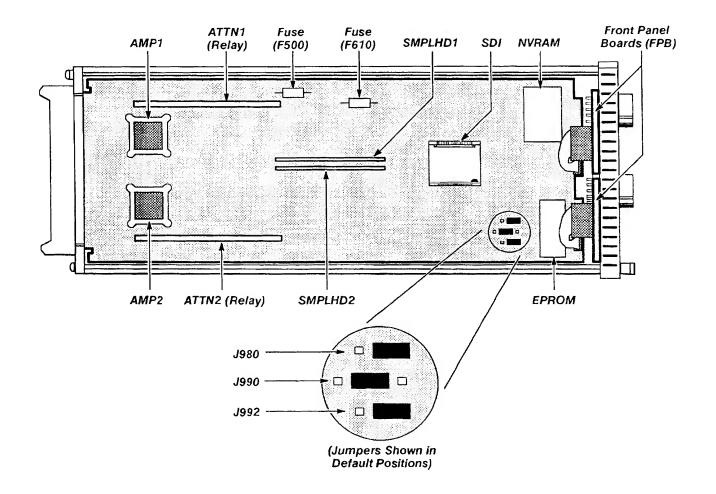
5 = 400 to 600 V

(The voltage equivalent is the voltage discharged from a 100 pF capacitor through a resistance of 100 Ω .)

Removing/Replacing FRUs

Once you have determined the suspect FRU remove the 11A16 side shields as discussed in the Preventive Maintenance section of Maintenance, find the FRU on the 11A16 Main board by referring to Figure 3-2, then refer to Table 3-8, to find the removal/replacement procedure(s).

The exploded-view drawing in *Replaceable Parts* can be useful in the removal/replacement procedures that follow.



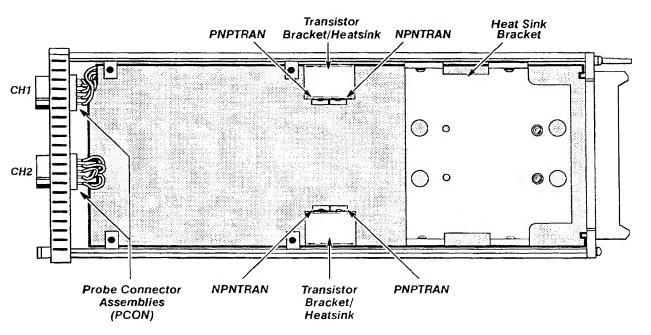


Figure 3-2 — FRU and FRU IC Locator

CAUTION

To avoid damage to the 11A16, set the mainframe ON/STANDBY switch to STANDBY, and remove the 11A16 from the mainframe before removing or replacing FRUs. If the mainframe green indicator light remains lit when the ON/STANDBY switch is in the STANDBY position, then the switch was internally disabled after the servicing of the Power Supply module. To enable the ON/STANDBY switch, refer to Corrective Maintenance in your mainframe Service Reference.

Table 3-8 — FRU Removal/Replacement Procedure Cross Reference

| FRU to be Replaced | Procedure(s) to Reference During Removal/Replacement | Page |
|--------------------|--|--------------|
| AMP1 or AMP2 | Removing/Replacing a Heat Sink Bracket 3-24 Removing/Replacing a Hypcon Assembly 3-25 Removing/Replacing a FRU IC 3-32 | |
| ATT1 or ATT2 | Removing/Replacing Heat Sink Bracket | |
| EPROM | Removing/Replacing a FRU IC | |
| PCON | Removing/Replacing a Front Panel Removing/Replacing a Connector Assembly Removing/Replacing a Muti-pin Connector | 3-21 3-17 |
| Front Panel | Removing/Replacing a Front Panel | 3-21 |
| FPB | Removing/Replacing a Front Panel | 3-31 |
| FUSE | Removing/Replacing a Fuse | 3-24 |
| Heat Sink Bracket | Removing/Replacing a Heat Sink Bracket | |
| Jumper | Removing/Replacing a Pin Jumper | 3-31 |
| Main board | Removing/Replacing an Attenuator3-16Removing/Replacing a Multi-Pin Connector3-31Removing/Replacing a Heat Sink Bracket3-24Removing/Replacing a Main board3-28Programming the Unit Identification3-35 | |
| NPNTRAN | Removing/Replacing Darlington Pair Power Transistors | 3-20 |
| NVRAM | Removing/Replacing a FRU IC | |
| PNPTRAN | Removing/Replacing a Darlington Pair Power Transistor | |
| RELAY (K1-K4) | Removing/Replacing a Relay | |
| SDI | Removing/Replacing a Slam Pack IC | |
| SMPLHD | Removing/Replacing a Sample and Hold board | |

Removing/Replacing an Attenuator Board

See Figure 3-3 for connector locations.

Remove an Attenuator board as follows:

Step 1: Disconnect the coaxial connector from the input of the Attenuator board.

Step 2: Carefully desolder the Attenuator board from the Main board.

Removal is easier if you first cut the pins at the base of the Attenuator board then desolder and pull each pin free from the Main board.

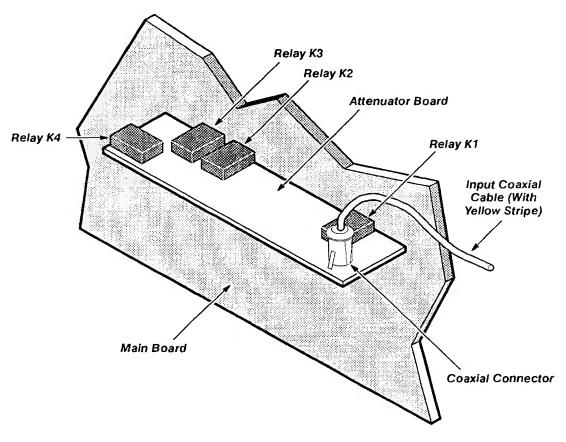


Figure 3-3 - Removing/Replacing an Attenuator

| | _ | |
|-----|------------|---|
| | Step 3: | Remove the Attenuator board from the Main board. |
| Rep | olace an a | attenuator as follows: |
| | • | Align the Attenuator board square pins with the cleared holes on the ard. The fifth pin is missing to aid in alignment. |
| | • | Note the proper orientation, then insert the Attenuator board into the cle on the Main board. |
| 0- | not onnh | y force to any subsempenents on the Attenuator board |

CAUTION

Do not apply force to any subcomponents on the Attenuator board.

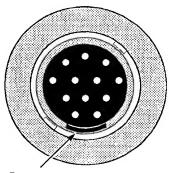
Step 3: Resolder the Attenuator board pins to the Main board connections.

Step 4: Reconnect the coaxial connector to the input of the Attenuator board. When engaging these connectors, use the following precautions: Ensure that the center conductor of the cable is straight. If necessary, straighten the conductor with clean pliers to avoid contamination. Insert the connector straight into the receptacle. While you insert the connector, look through the slot in the outer receptacle to ensure that the center conductor enters its receptacle properly. Removing/Replacing the Connector Assembly See Figures 3-2, 3-4, 3-5, 3-7, 3-10, and 3-12 for connector wiring, and the locations of screws and index marks. You can verify a faulty connector by trying a known good probe. Remove the connector assembly as follows: Step 1: Remove the Front Panel (See Removing/Replacing the Front Panel). Step 2: Disconnect the coaxial connector at the Main board and at the Attenuator board. Disconnect the 10-pin connector from the Main board. Step 3: Disconnect the multi-pin connectors that connect the Front Panel boards to the Main board. (Note the position of the multi-pins index triangle to ensure that you can correctly replace this connector.) Step 4: Remove the four Torx head screws (see Fig. 3-7) that secure the current probe connector assembly to the front subpanel. Step 5: Slip the nut plate out of the way to gain access to the faulty probe connector. Step 6: Remove the current probe connector assembly from the 11A16. Replace the current probe connector assembly by referring to Figures 3-4 and 3-5 then proceeding as follows: Step 1: Align the 12-pin connector with the tang slot at the bottom as shown

Step 2: Insert the 12-pin connector through the Front Panel from the rear. Put

the nut plate on behind the connectors.

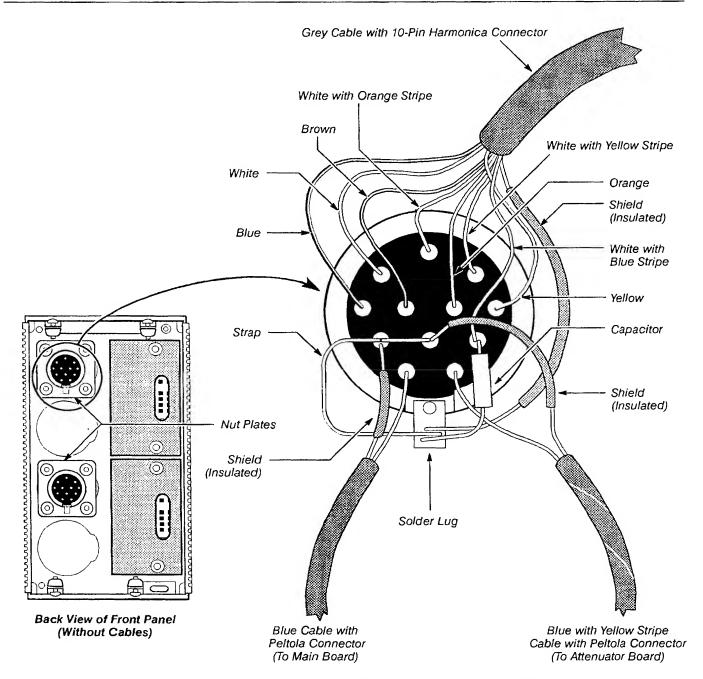
in Figure 3-4.



Tang Slot at Bottom

Figure 3-4 — Proper Orientation of the Current Probe Connector

| • | Heplace the four look head screws that secure the connector and nut the front subpanel. |
|-----------------------|--|
| Step 4: | Reconnect the 10-pin connector to its receptacle on the Main board. |
| Attenuate board. E | Connect the coaxial cable with a <i>yellow stripe</i> to the appropriate or board and connect the coaxial cable with <i>no stripe</i> to the Main nsure that the center conductor of the coaxial wire is straight. If ry, straighten the conductor with clean pliers to avoid contamination. |
| Step 6: the Main | Reconnect the multi-pin connectors from the Front Panel boards to board. |
| Step 7: | Replace the Front Panel (See Removing/Replacing the Front Panel). |



Wiring of Front Panel Connectors (Viewed From Back of Connector)

Figure 3-5 — Installation Wiring for Current Probe Connector

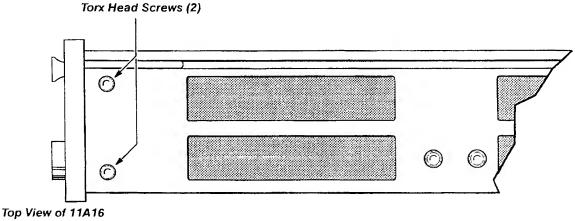
Removing/Replacing a Darlington Power Transistor

To check the transistors in circuit, ensure that the power is off, then set a digital multimeter to the 1 $k\Omega$ range and measure the emitter to collector (two outside pins) resistance. This should measure 2 $k\Omega$ or greater in circuit, with or without a good fuse and if the transistors are not shorted collector-to-emitter (the most common failure mode). You can also identify the emitter and collector by the square board pad for the emitter and the the heatsink tab tied to the collector. We recommend that both transistors of a pair be replaced, even if only one appears defective. Refer to Figure 3-2 and remove a transistor pair as follows:

| 1010 | ctive. Here to Figure 0-2 and remove a transistor pair as follows. | | | |
|---|---|--|--|--|
| _ | Step 1: Remove the Torx screws that hold the transistor heatsink bracket to the plug-in side rail. | | | |
| | Step 2: Remove the Torx screws that hold the transistor pair to the heatsink bracket. Save the heat transfer material for reinstallation. | | | |
| | Step 3: Desolder the transistors from the Main board. | | | |
| Rep | ace a transistor by: | | | |
| | Step 1: Orient the new transistors properly onto the heatsink, aligning the tab holes with the threaded hole in the heatsink. Note that the NPN is on the right and PNP is on the left (see Fig. 3-2). | | | |
| | Step 2: Place the heat transfer material between the transistor tab and the heatsink and install the Torx screws, shoulder washers, and flat washers to secure the transistors to the heatsink. Do not tighten the screws at this time. Refer to the exploded view, Figure 5-1. | | | |
| | Step 3: Place (but do not solder) the full length transistor leads in the appropriate Main board holes, then install the heatsink on the plug-in side rail. | | | |
| | Step 4: Solder the transistors to the Main board. Now tighten the Torx screws securing the Darlington Pair transistors to the heatsink. This assembly order minimizes stress on the transistor leads. | | | |
| Removing/Replacing a Sample and Hold Board | | | | |
| The diagnostics are the primary means for troubleshooting Sample and Hold boards. Refer to Figure 3-2 to identify the two Sample and Hold boards. | | | | |
| Remove a Sample and Hold board as follows: | | | | |
| | Step 1: Carefully desolder the Sample and Hold board from the Main board. | | | |
| | Step 2: Remove the Sample and Hold board from the Main board taking care not to pull any pads loose. | | | |
| Re | place a Sample and Hold board as follows: | | | |
| | Step 1: Align the Sample and Hold board square pins with the cleared holes on the Main board. The gap in the line of pins ensures correct mounting. | | | |

3-20

| | Step 2: Note the proper orientation, then insert the Sample and Hold board into the receptacle on the Main board. |
|-----------|---|
| EAUTION § | Do not apply force to any subcomponents on the Sample and Hold board. |
| ¿s | Step 3: Resolder the Sample and Hold board pins to the Main board connections. |
| | Removing/Replacing the Front Panel |
| | See Figures 3-6 and 3-7 for connector and screw locations. |
| | Remove the front panel as follows: |
| | Step 1: Unhook the return spring, located on the bottom of the 11A16, from the release bar (retain this return spring). |
| | Step 2: Remove the four Torx head screws (two on the bottom and two on the top of the front panel) that secure the front subpanel to the top and bottom frames. |
| | Step 3: Pull the release bar out of the 11A16 as far as possible. Leave the release bar in this position. |
| | Step 4: Insert a slender, sharp tool (such as a scribe) between the subpanel, at the notch around the release bar, and the front panel. |
| | Step 5: Carefully separate the front panel from the subpanel. (Do not bend the front panel; it is intentionally bowed at the center.) |
| | Step 6: Remove the front panel from the 11A16. |



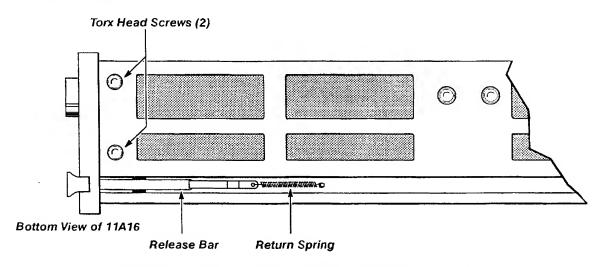


Figure 3-6 — Removing/Replacing the Front Panel Retainer Screws

Replace the front panel as follows:

- Step 1: Ensure that the four screws that secure the front subpanel to the top and bottom frames are removed.
- Step 2: Ensure that the release bar return spring is removed.
- Step 3: Position the 11A16 on its side, with the front panel facing towards you.
- Step 4: Pull the release bar out of the 11A16 as far as possible, and then leave the release bar in this position.
- Step 5: Position the front panel so that the notch in the bottom fits over the release bar rod, then carefully insert the four front-panel tabs into the slots in the front subpanel. (If needed, carefully pull the top and bottom frames away from the subpanel to allow the front panel tabs to fit between the casting and the frames. Remove the screws holding the transistor heatsinks to the side rails if more than 1/8" spreading is necessary.)

- Step 6: Carefully press the edges of the front panel into place around the push buttons and the outer edges of the front panel.
- Step 7: Replace the four Torx head screws that secure the front subpanel to the top and bottom frames.
- Step 8: Replace the release bar return spring; orienting the spring so that its loop fits over the frame hook, flat against the frame section.

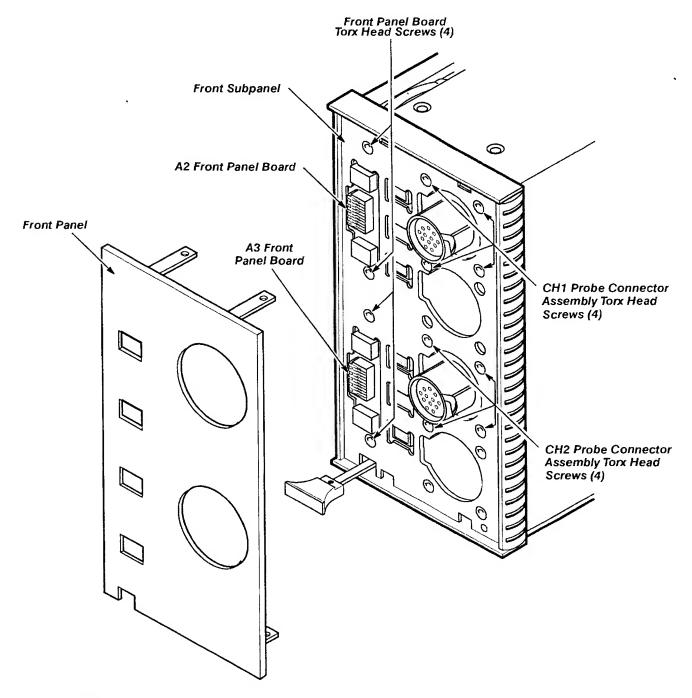
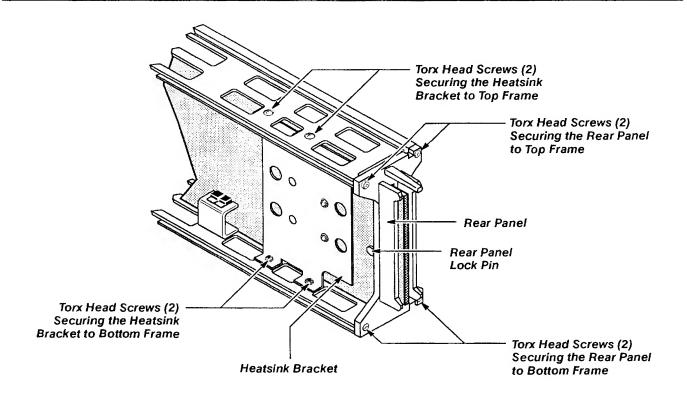


Figure 3-7 -- Removing/Replacing the Probe Connectors, Front Panel, and the Front Panel Boards

| | Removing/Replacing a Front Panel Board | | | |
|--|---|--|--|--|
| See Figures 3-7, 3-6, and 3-12 for connector, screw, and index locations. A connuity check between the Front Panel and Main board connector will verify a fau | | | | |
| Remove and replace the Front Panel board as follows: | | | | |
| Step 1: Disconnect the multi-pin connector that connects from the From Panel board to the Main board. Note the position of the multi-pin connect index triangle to ensure that this connector can be correctly replaced. | | | | |
| | Step 2: Remove the two Torx head screws that secure the Front Panel board to the front subpanel. | | | |
| | Step 3: Remove the Front Panel board. | | | |
| | To replace the Front Panel board, perform the previous steps in the reverse order. | | | |
| | Removing/Replacing a Fuse | | | |
| | See Figure 3-2 (FRU locator) for fuse locations. A fuse will usually fail only when a Darlington transistor has failed. | | | |
| | Remove fuses as follows: | | | |
| | Step 1: Desolder the faulty fuse from the Main board. | | | |
| | Step 2: Resolder the correct value of fuse to the Main board. | | | |
| | Step 3: When a fuse is blown, it is likely that one or both Darlington power transistors will be faulty. Troubleshoot these before continuing. The only function of these fuses is to supply current to the Darlington transistors and protect associated circuitry from excessive current flow. | | | |
| | Removing/Replacing the IC Heatsink Bracket | | | |
| | See Figure 3-8 for screw locations. Remove and replace the IC heatsink bracket as follows: | | | |
| | Step 1: Remove the four Torx head screws that secure the plastic rear panel to the top and bottom frames. | | | |
| | Step 2: Carefully press the rear-panel lock pin out of the alignment hole in the Main board and remove the plastic rear panel from the 11A16. | | | |
| | Step 3: Remove the two Torx head screws that secure the heatsink bracket to the Main board. | | | |
| | Step 4: Remove the four Torx head screws securing the heatsink bracket to the top and bottom frames. Take care not to spread the top and bottom frames which could damage the Darlington Pair power transistors. If necessary, remove the screws securing the transistor heatsink to the side rail. | | | |
| | Step 5: Slide the heatsink bracket out the rear of the frame. Be careful not to damage the leads of the power transistors. | | | |
| | To replace the heatsink bracket, perform the previous steps in the reverse order. | | | |

3-24 Maintenance



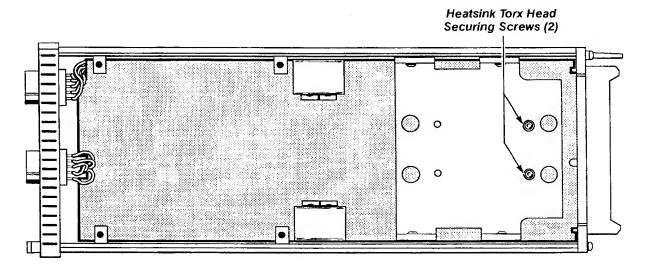
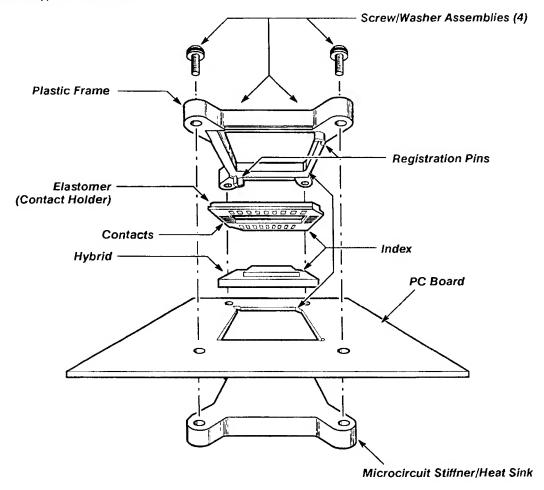


Figure 3-8 — Removing/Replacing the Heatsink Bracket

Removing/Replacing the Hypcon Assembly

The Hypcon (Hybrid-printed circuit connector) Assembly connects a hybrid IC to the Main board. A hybrid IC can be an amplifier or other device that has been integrated onto a ceramic substrate. The Hypcon Assembly requires special care. When replacing the Hypcon do not touch the elastomer or hybrid gold-plated contacts with your fingers.

Exploded View of Hypcon Connector



Cross Section View of Hypcon Connector

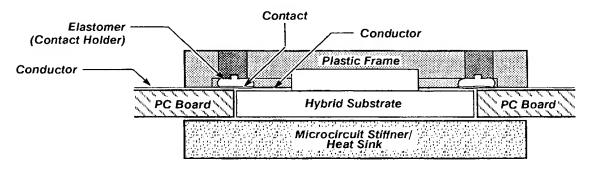
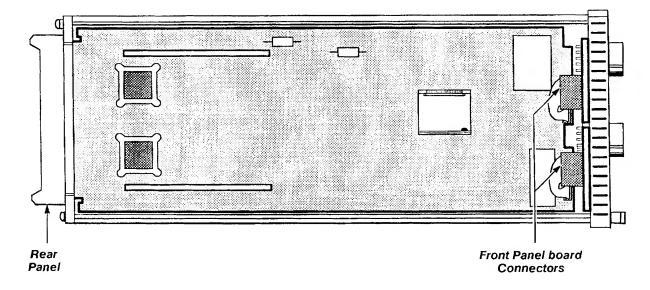


Figure 3-9 — Removing/Replacing the Hypcon Assembly

Note: All work on Hypcon assemblies should be performed in a dust free environment to avoid contamination of contacts.

| | nemove the hypcon assembly as follows. |
|-------------|--|
| | Step 1: Notice the index on the Main board (arrow) and the plastic frame (pointed tab). |
| | Step 2: Unscrew and remove the four Torx head screw/washer assemblies. |
| | Step 3: Lift the plastic frame from the Main board. |
| | Step 4: Notice the index location of the hybrid, and remove the hybrid from Main board with the tweezers. |
| | Note: Step 5 describes the removal of the elastomer from the plastic frame. This step is unnecessary when replacing the hybrid only. |
| | Step 5: Notice the index location of the elastomer (contact holder). Grasp and lift the corner of the contact holder with the tweezers to remove the holder from the plastic frame. |
| | Replace the Hypcon Assembly as follows: |
| | Before remounting the Hypcon assembly, use a 4X (or greater) magnifying glass to examine the hybrid, elastomer, and the Hypcon contacts for dust, hair, lint, or other foreign matter. If the Main board surfaces require more cleaning, then scrub the surface with a soft rubber eraser and blow on, or vacuum, the surface while dusting it with a small clean brush. If the hybrid and elastomer contact holders are contaminated, then flush or spray the holders with alcohol. |
| CAUTION | Do not scrub with a cotton-tipped swab or similar device, since cotton fibers may adhere to the contacts. |
| E CAUTION § | Special care must be taken to ensure correct index alignment of each Hypcon part while reassembling; since failure to do so can result in a cracked hybrid substrate. |
| | Steps 1-3 are not necessary if you are replacing the hybrid only. |
| | Step 1: Grasp a corner of the elastomer with the tweezers, and place the elastomer into the plastic frame. |
| | Step 2: Align the keyed corner of the elastomer with the keyed corner of plastic frame. |
| | Step 3: Tamp the elastomer into the plastic frame uniformly. |
| | Note: Keeping the elastomer clean is very important. Small hairs and elastomer flash under the contacts can prevent good electrical contact. Most apparent failures of the hybrid are due to contamination of the Hypcon. |

| | Step 4: Place the hybrid into the square hole in the Main board. (The hybrid is keyed so that it will fit into the Main board in only one orientation. When the back of the hybrid rests on the heatsink pedestal, the top of the hybrid should be flush with the top of the Main board.) | | |
|---|--|--|--|
| | Step 5: Place the plastic frame, with the elastomer installed, over the hybrid so that the key (pointed tab) aligns with the corner arrow on the board. | | |
| | Step 6: Replace the four Torx head screw/washer assemblies, and apply two inch-pounds of torque, (2.3 cm-kg) to secure the connector assembly. Do not overtighten the assembly as this may strip the microcircuit stiffener/heatsink mounting threads. | | |
| Rer | noving/Replacing the Main Board | | |
| See Figures 3-3, 3-8, 3-10, 3-11, 3-12, and the exploded view in the <i>Replaceable Parts</i> section for connector, screw, and index locations. The Darlington transistor pairs including their heatsinks must be saved for use on the new Main board. | | | |
| Ren | nove the Main board as follows: | | |
| | Step 1: Disconnect the multi-pin connectors that connect from the Front Panel boards to the Main board. (Note the position of the multi-pin connector index triangle to ensure proper reassembly.) | | |
| | Step 2: Disconnect the 10-pin probe connectors from the Main board. Disconnect the coaxial cables from the Main board and Attenuator boards. | | |
| | Step 3: Remove the four screws that secure the Darlington Pair transistor heatsinks to the top and bottom side rails. | | |
| | Step 4: Remove the four Torx head screws that secure the plastic rear panel to the top and bottom frames. | | |
| | Step 5: Carefully pull the rear-panel lock pin out of the alignment hole in the Main board, and remove the plastic rear panel from the 11A16 (see Fig. 3-8). | | |
| | Step 6: Remove the four Torx head screws that secure the hybrid heatsink bracket to the top and bottom frames. | | |
| | Step 7: Remove the six Torx head screws and nut blocks that secure the Main board to the top and bottom frames. | | |
| | Step 8: Carefully withdraw the Main board between the frames and remove it from the 11A16. | | |
| | Step 9: If the Main board is being replaced, remove the Darlington Pair transistors, still mounted on their heatsinks, from the old Main board. Leaving the transistors attached to their heatsink will guarantee proper reinstallation in the new Main board. The transistor sets are interchangeable through the PNP and NPN transistors of a set must be correctly placed. Figure 3-2 shows the correct transistor orientation. | | |



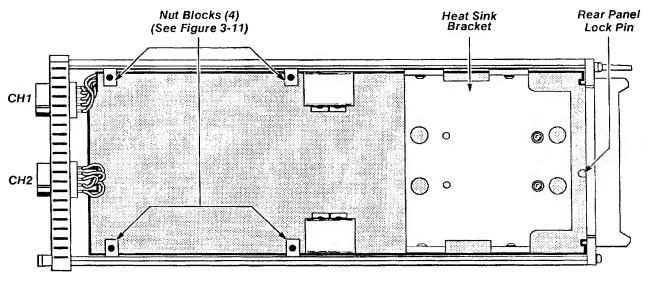


Figure 3-10 — Removing/Replacing the Main Board

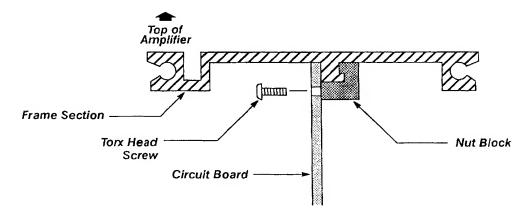


Figure 3-11 — Torx Screw and Nut Block Orientation

| iten | ou are replacing a Main board with a new one, you will need to remove two as from the old Main board: the IC Heat Sink bracket and the two pair of lington Pair transistors with heatsinks. Replace the Main board as follows: |
|------|---|
| | Step 1: Lay the 11A16 on its side with the pushbuttons facing upwards. This will allow the Main board to be slid into place, component side up. |
| | Step 2: Carefully insert the Main board between the frames until the plastic rear panel contacts the top and bottom frames. (The board fits atop the center ridges on the top and bottom frames.) |
| | If you are installing a new Main board, first attach the plastic rear panel, from the old board, to the new Main board. The rear panel helps position the Main board when its rear-panel lock pin is correctly seated in the Main board. |
| | Step 3: Replace the four Torx head screws that secure the heatsink bracket to the top and bottom frames. The heatsink bracket and the rear panel ensure correct front/back position for the Main board. Refer to Figure 3-8 for screw placement. |
| | If you are installing a new Main board, first mount the large flat heatsink bracket from the old board on the back of the new Main board. Heatsink installation is described on page 3-24. |
| | Step 4: Replace the four Torx head screws that secure the rear panel to the top and bottom frames. |
| | Step 5: Replace the six Torx head screws and nut blocks that secure the Main board to the top and bottom frames. |
| | Step 6: Replace the four screws that secure the Darlington Pair transistor heatsink to the top and bottom rails. If the transistors are already soldered into the Main board, loosen the screws holding the transistors to their heatsinks before attaching the heatsinks to the side rails. This will reduce the likelihood of component damage. |
| | If you are installing a new Main board, first remove the Darlington Pair transistors with their heatsinks from the old board and install them in the new Main board (do not solder yet). |
| | Step 7: Reconnect the 10-pin probe connectors into their receptacles on the Main board. Connect the probe coaxial cables to the Main board and Attenuator boards. |
| | Step 8: Reconnect the multi-pin connectors from the Front Panel boards to the connectors on the Main board. |
| | Step 9: Replace the attenuators (see <i>Removing/Replacing an Attenuator</i> in this section). |
| | Step 10: If the Main board has been replaced, then the Unit Identification (UID) number needs to be re-entered (refer to <i>Programming the Unit Identification</i> on page 3-35.) |

Removing/Replacing Multi-Pin Connectors

This section describes the multi-pin connectors found on the 11A16. Pin 1 on a multi-pin connector is designated with a triangle (or arrowhead) on the holder. This triangle is indexed to a square pad on the board that denotes pin 1.

A gap between the pin 1 and 3 positions in the holder keys a multi-pin connector. There is a corresponding gap between pins 1 and 3 on the board. (A small plastic plug covers the pin 2 position on the end of the holder.)

Align the plastic plug of the holder with the gap between the board pins (see Fig. 3-12).

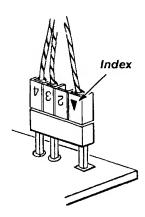


Figure 3-12 - Multi-Pin Connector Orientation

Removing/Replacing a Pin Jumper

Three jumpers, J980, J990, and J992, are installed in the 11A16 for normal operation. See Figure 3-2 for the location and standard configuration of these jumpers.

All jumpers should normally be installed across Pins 2 and 3.

Removing/Replacing a Relay

The relays K1-K4 are located on the Attenuator board. Refer to Figure 3-3. It may be necessary to remove the top side rail to access the pins of a suspect relay. Refer to *Removing/Replacing the Main board* on page 3-28.

Remove a Relay as follows:

Step 1: Desolder the Relay from the Attenuator board.

Replace a Relay as follows:

Step 1: Orient pin 1 of the Relay (the end with a white bar) toward the square circuit pad before soldering.

Removing/Replacing a DIP FRU IC

The Main board has several dual-inline-package (DIP) ICs that are replaceable in the field. For Hypcon IC replacement refer to Removing/Replacing the Hypcon Assembly earlier in this section.



Observe all the special precautions mentioned under Static-Sensitive Device Classification on page 3-12. Avoid touching the IC or the socket contacts with your fingers as finger oils can lessen reliability.

Do not remove the label affixed to the top of any EPROM. Removing this label will allow light into the IC which may erase data. This also removes critical firmware version information.

If you are required to desolder an IC from the Main board it is suggested that you install a good quality IC socket. A socket saves wear and tear on the Main board when multiple exchanges of an IC are necessary.

See Figures 3-13 and 3-14 for equipment and indexing information.

| Remove an FRU IC in a DIP socket as follows: |
|--|
| Step 1: Use IC insertion-extraction pliers positioned around the outside of the IC. Figure 3-13 shows an example of this type of pliers. |
| Step 2: Squeeze the handles to grasp the IC, lightly compressing the pins and slowly pull the IC from the socket. Place the removed IC on a static free surface or IC holder. |
| Avoid touching the IC pins or socket contacts with your fingers. Finger oils can lessen contact reliability. Also, touching the pins can induce static-discharge damage should the IC need to be reused. |

CAUTION

Replace an FRU IC in a DIP socket as follows:

| Step 1: Place the IC on a static free surface, then grasp the IC with the IC |
|---|
| insertion-extraction pliers; ensuring that all the pins of the IC are straight and lightly compressed. Do not use the IC label as an index, instead locate the index on the body of the IC. |
| Step 2: Align the IC index slot with that of the socket. (Fig. 3-14 gives an illustration of this indexing.) |

Step 3: Align the pins with their respective socket contacts.

Step 4: Press the IC slowly and evenly into its socket. Ensure that the IC is firmly seated in its socket.

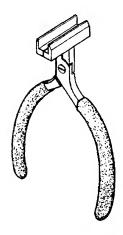


Figure 3-13 - IC Insertion-Extraction Pliers

Removing/Replacing a "Slam-Pack" IC

A Slam-Pack IC is indexed to its socket by a beveled corner. The other corners are notched to fit the edges of the socket. The beveled corner aligns with a spring (small metal tab) at one corner of the socket.

Remove the Slam-Pack IC as follows: Step 1: To remove the retaining clip, hold the heatsink cover in place and move the retaining clip off the tabs while pushing down slightly on the cover. Step 2: Slowly remove the cover to prevent the IC from falling out. (Note the position of the index on the IC to ensure that this IC can be correctly replaced.) Step 3: Remove the IC with tweezers. Avoid touching the IC or the socket contacts with your fingers. Finger oils **CAUTION** can lessen reliability. Replace the Slam-Pack IC as follows: Step 1: Using tweezers, place the beveled corner of the replacement IC against the index spring. Do not damage the spring with the beveled corner; this could cause a short **CAUTION** in the two corner contacts. Step 2: Using the tweezers, arrange the other corners of the IC to fit evenly at the socket edges. Step 3: Set the cover flat on the IC with the cover end tabs aligned with the mating recesses of the socket. Be sure the end tabs are not inserted yet. Step 4: Push the cover down, keeping the cover flat on the IC, and slide the cover end tabs into place. Hold the cover then move the retaining clip over the tabs on the other end of the cover.

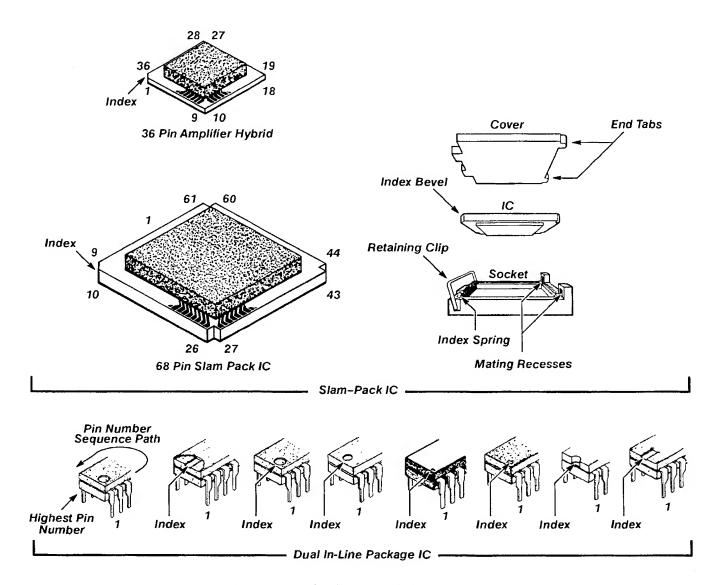


Figure 3-14 — Semiconductor Indexing Diagram

Programming the Unit Identification

This section discusses the procedure to enter the Unit Identification (UID) into the 11A16 nonvolatile RAM (NVRAM). The UID is identical to the serial number of the 11A16, and is stored in NVRAM. You will need to enter this number if the Main board is replaced or if data in NVRAM becomes corrupted.

| Enter the UID as follows: | | | |
|---|--|--|--|
| | Step 1: Connect your terminal to the RS-232-C port of the mainframe. (I to the User Reference manual of your mainframe for instructions on setting the RS-232-C parameters.) | | |
| | Step 2: Configure the mainframe jumper that allows programming of calibration constants and the mainframe Unit Identification (often referred to as the Cal Lock jumper). Refer to the mainframe Service Reference for instructions on locating and setting the Cal Lock jumper. | | |
| | jumper. (| Move the jumper J990 on the Main board so that it covers the two jumper pins (pins 1-2). Refer to Figure 3-2 for the location of this Obtain the 11A16 serial number from the printed tag on the 11A16 rail Front Panel. | |
| | Step 4: | Install the 11A16 in any compartment. | |
| | Step 5: | Set the ON/STANDBY switch to ON. | |
| | Step 6: | Wait until the diagnostic tests are completed. | |
| | Step 7: | On your terminal, type the command: | |
| | UID [Left Center Right]:" <serial number="">"</serial> | | |
| Left Center Right refers to the compartment that the 11A16 resides. | | | |
| | Step 8: | On the terminal, type the query: | |
| | UID? [L | eft Center Right] | |
| | Observe | e that the correct UID is reported. | |
| | Step 9: | Set the ON/STANDBY switch to STANDBY. | |
| | Step 10: | Remove the 11A16. | |
| | Step 11: position position | (across pins 2-3). Reset the mainframe Cal Lock jumper to its normal | |
| | u can use ep 6. | this procedure to confirm the UID by repeating all steps except | |

3-36 Maintenance

Theory of Operation

This section provides a typical signal processing cycle and descriptions of the major circuitry blocks of the 11A16 Two-Channel Current Amplifier. Figure 4-1 shows the functional blocks of the 11A16.

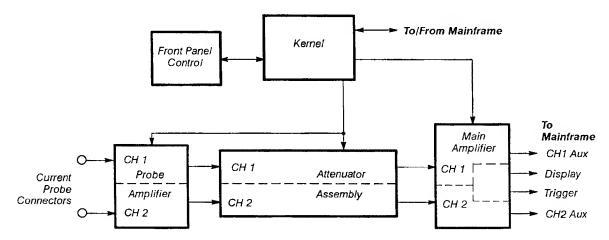


Figure 4-1 — 11A16 System Functional Block Diagram

Typical Signal Processing Cycle

The following sequence is a brief overview of how the 11A16 acquires and processes a signal (see Figs. 4-1 and 4-2):

- Step 1: Analog input signals are acquired from two sources in the current probe: the Hall Effect device and the probe winding.
- Step 2: The Hall Effect device signal is passed through the Hall Effect amplifier, the Power amplifier, then back to one side of the probe winding.
- Step 3: The attenuator assembly receives the signal from the other side of the probe winding. It provides the input coupling mode (AC, DC, or OFF), and attenuation.
- Step 4: The Kernel block generates offset voltages for the Hall Effect amplifier, the Power amplifier, and the Main Amplifier. The Kernel block also reads and drives the Front Panel Control block.
- Step 5: The Main Amplifier block receives the signal from the Attenuator block. It subtracts the offset voltage from the input signal then amplifies the difference.
- Step 6: The Main Amplifier block then amplifies and replicates this difference signal to three independently buffered outputs: display, trigger, and CH 1 or CH 2 auxiliary.
- Step 7: The Kernel block provides ON/OFF control for all the amplifier block outputs along with Normal/Invert control signals for the display and trigger outputs.

Detailed Block Diagram Descriptions

This section describes and illustrates the analog and digital circuitry of the 11A16 block diagram (see Fig. 4-2).

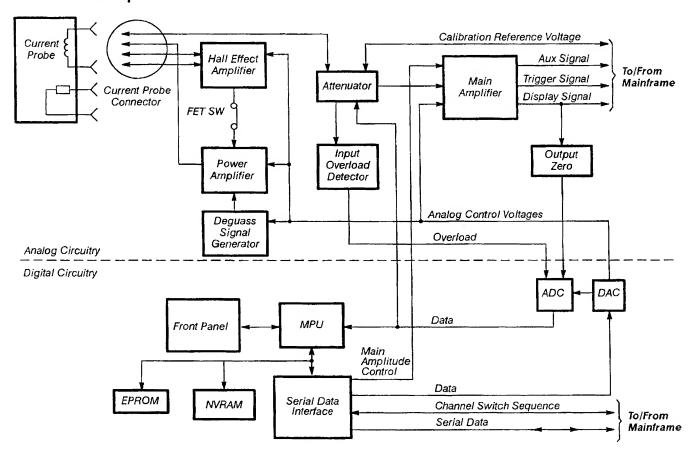


Figure 4-2 - 11A16 Detailed Block Diagram (One Analog Channel)

Analog Circuitry

The analog circuitry processes the input signal. It provides attenuation and amplification to an input signal before it is passed to the mainframe.

Attenuators – There is one attenuator for each channel. Both identical attenuators are located on the Main board. They provide the following functions:

- signal attenuation
- input coupling modes
- calibration reference signal

Attenuation of a signal is selected by activating relays that connect two attenuators in series. The relays can be activated in specific combinations to produce three different attenuation factors: 1, 10, or 100.

The input coupling mode is set with two relays on the attenuator modules. The input coupling mode can be set to AC, DC, or OFF.

During calibration and Self-Tests, a calibration reference signal is connected to the input of the attenuator and an auxiliary 50 Ω termination is connected to the input connector.

Main Amplifiers – amplify the difference between the input channel signal and the DC offset voltage by 1, 2.5, 5, 10, 25, or 50 thus providing gain switching to the input signals. The Channel 1 and Channel 2 amplifiers each produce three output signals: Display, Trigger, and CH 1 and CH 2 auxiliary signals, respectively. The Display and Trigger signals from CH 1 and CH 2 are connected together (summed). Each of these signals can be independently inverted or switched off. An Input Overload Detection block protects the attenuator and amplifier from input voltage levels in excess of 2 V peak (@1 mA – 50 mA /div) and input power levels in excess of 2.0 W peak (@100 mA – 2 A/div).

The ADC—reads the analog probe data, current/voltage probe sense, overload detector, output zero voltage, and assorted diagnostic signals and converts these to digital signals. These signals are monitored by the MPU.

The DAC – converts digital data originating from the MPU into analog control voltages for the Hall Effect device Amplifier, the Power Amplifier, and the Main Amplifier.

The Hall Effect Device Amplifier – amplifies the small input signal, originating from the Current Probe Hall Effect Sensor, by 100.

The Power Amplifier – increases the Hall Amplifier signal to a level capable of driving the Current Probe winding with current levels up to 250 mA.

The Degauss Signal Block – generates a 180 Hz signal with an exponentially decreasing amplitude. This signal drives the Power Amplifier when the FET switch is open. Its purpose is to demagnetize the core of a connected Current Probe.

The Output Zero Block—provides feedback to the ADC and MPU when the degauss function is invoked. This information is required to accurately zero the display trace during the Degauss Cycle.

Digital Circuitry

The Digital Circuitry (Kernel block) performs the following major functions:

- Monitors the front panel buttons and probe information.
- Interprets commands from the mainframe, then sets the appropriate signal path configuration.
- Controls the Analog Control Voltage System (ACVS).
- Manages the amplifier diagnostics and calibration.

The MPU – receives information from the mainframe that allows it to control the amplifiers and the attenuators.

The EPROM – stores the program code. The MPU uses this code to execute its functions.

The NVRAM – stores information such as the amplifier calibration constants, the amplifier serial number, probe calibration constants, and the ID of the most recent host mainframe.

The Serial Data Interface (SDI) (or Housekeeping) IC—controls the Main Amplifier, the DAC, and an array of sample and hold circuits, to create 16 analog control voltages (ACVS). When more than one channel is ON, the MPU stores the channel switching sequence in the SDI IC.

The SDI IC contains a receiver and transmitter for serial communications between the 11A16 and the mainframe. The SDI IC converts parallel (eight-bit) data bytes from the MPU into a serial data signal. This serial data is then sent to the mainframe. Conversely, the SDI IC converts the serial data from the mainframe into parallel data bytes for the MPU to read.

Front Panel Block

The Front Panel Control block communicates the status of the front panel buttons to the MPU block. The board contains two LED's and two push buttons per channel. The MPU will turn on a channel On LED when the display On push button is pressed.

Current Probe

The Current Probe contains a winding and a Hall Effect Sensor that convert electrical current in a conductor to voltage signals for the plug-in unit. The winding provides high frequency signals and the Hall Effect Device provides DC and low frequency signals.

Replaceable Parts

This section contains a list of the components that are replaceable for the 11A16 Two-Channel Amplifier. As described below, use this list to identify and order replacement parts.

Parts Ordering Information

Replacement parts are available from or through your local Tektronix, Inc. service center or representative.

Changes to Tektronix instruments are sometimes made to accommodate improved components as they become available and to give you the benefit of the latest circuit improvements. Therefore, when ordering parts, it is important to include the following information in your order:

- Part Number
- Instrument Type or Model Number
- Instrument Serial Number
- Instrument Modification Number, if applicable

If a part you order has been replaced with a different or improved part, your local Tektronix service center or representative will contact you concerning any change in the part number.

Change information, if any, is located at the rear of this manual.

Module Replacement

The 11A16 Two-Channel Amplifier is serviced by module replacement so there are three options you should consider:

Module Exchange—In some cases you may exchange your module for a remanufactured module. These modules cost significantly less than new modules and meet the same factory specifications. For more information about the module exchange program, call 1-800-TEKWIDE, extension BV 5799.

Module Repair—You may ship your module to us for repair, after which we will return it to you.

New Modules—You may purchase new replacement modules in the same way as other replacement parts.

Using the Replaceable Parts List

The tabular information in the Replaceable Parts List is arranged for quick retrieval. Understanding the structure and features of the list will help you find the all the information you need for ordering replacement parts.

Item Names

In the Replaceable Parts List, an Item Name is separated from the description by a colon (:). Because of space limitations, an Item Name may sometimes appear as incomplete. For further Item Name identification, U.S. Federal Cataloging Handbook H6-1 can be used where possible.

Indentation System

This parts list is indented to show the relationship between items. The following example is of the indentation system used in the Description column:

1 2 3 4 5

Name & Description

Assembly and/or Component

Attaching parts for Assembly and/or Component

(END ATTACHING PARTS)

Detail Part of Assembly and/or Component Attaching parts for Detail Part

(END ATTACHING PARTS)

Parts of Detail Part Attaching parts for Parts of Detail Part (END ATTACHING PARTS)

Attaching Parts always appear in the same indentation as the item it mounts, while the detail parts are indented to the right. Indented items are part of, and included with, the next higher indentation. Attaching parts must be purchased separately, unless otherwise specified.

Abbreviations

Abbreviations for the FRU boards listed in Table 5-1 conform to American National Standards Institute (ANSI) standard Y1.1. Other FRUs are listed on page NO TAG.

Table 5-1 - Board FRUs

| FRU | Part Number | Description |
|------|-------------|-------------------|
| A1 | 671-1448-00 | Main Board |
| A1A1 | 670-8986-00 | Sample/Hold Board |
| A1A2 | 670-8986-00 | Sample/Hold Board |
| A1A3 | 671-1451-01 | Attenuator Board |
| A1A4 | 671-1451-01 | Attenuator Board |
| A2 | 670-9336-00 | Front Panel Board |
| A3 | 670-9336-00 | Front Panel Board |

CROSS INDEX - MFR. CODE NUMBER TO MANUFACTURER

| Mfr. Code | Manufacturer | Address | City, State, Zip Code |
|---------------|---|--------------------------------------|------------------------------|
| TK0435 | LEWIS SCREW CO | 4300 S RACINE AVE | CHICAGO IL 60609-3320 |
| TK0860 | LABEL GRAPHICS | 6700 SW BRADBURY CT | PORTLAND OR 97224 |
| TK1163 | POLYCAST INC | 9898 SW TIGARD ST | TIGARD OR 97223 |
| TK1326 | NORTHWEST FOURSLIDE INC | 18224 SW 100TH CT | TUALATIN OR 97062 |
| TK1465 | BEAVERTON PARTS MFG CO | 1800 NW 216TH AVE | HILLSBORO OR 97124-6629 |
| TK1572 | RAN-ROB INC | 631 85TH AVE | OAKLAND CA 94621-1254 |
| TK1689 | AROMAT CORP | 10400 N TANTAU AVE | CUPERTINO CA 95014-0708 |
| TK1943 | NEILSEN MANUFACTURING INC | 3501 PORTLAND ROAD NE | SALEM OR 97303 |
| TK1967 | SYNDETEK | 3915 E MAIN | SPOKANE WA 99202 |
| 0JR05 | TRIQUEST CORP | 3000 LEWIS AND CLARK HWY | VANCOUVER WA 98661-2999 |
| 0KB01 | STAUFFER SUPPLY | 810 SE SHERMAN | PORTLAND OR 97214 |
| 0KB05 | NORTH STAR NAMEPLATE | 1281-S NE 25TH | HILLSBORO OR 97124 |
| 03888 | KDI ELECTRONICS | 60 S JEFFERSON RD | WHIPPANY NJ 07981-1001 |
| 04713 | MOTOROLA INC SEMICONDUCTOR PRODUCTS SECTOR | 5005 E MCDOWELL RD | PHOENIX AZ 85008-4229 |
| 12327 | FREEWAY CORP | 9301 ALLEN DR | CLEVELAND OH 44125-4632 |
| 2K262 | BOYD CORP | 6136 NE 87th AVE PO BOX 20038 | PORTLAND OR 97220 |
| 22526 | DU PONT E I DE NEMOURS AND CO INC DU PONT ELECTRONICS DEPT | 515 FISHING CREEK RD | NEW CUMBERLAND PA 17070-3007 |
| 22599 | AMERACE CORP ESNA DIV | 15201 BURBANK BLVD SUITE C | VAN NUYS CA 91411-3532 |
| 5Y400 | TRIAX METAL PRODUCTS INC DIV OF BEAVERTON PARTS MFG CO | 1800 216TH AVE NW | HILLSBORO OR 97124-6629 |
| 66302 | VLSI TECHNOLOGY INC | 1109 MCKAY DR | SAN JOSE CA 95131-1706 |
| 71400 | BUSSMANN DIV OF COOPER INDUSTRIES INC | 114 OLD STATE RD PO BOX 14460 | ST LOUIS MO 63178 |
| 7374 3 | FISCHER SPECIAL MFG CO | 111 INDUSTRIAL RD | COLD SPRING KY 41076-9749 |
| 8X345 | NORTHWEST SPRING & MFG CO | 5858 WILLOW LANE | LAKE OSWEGO OR 97034-5343 |
| 80009 | TEKTRONIX INC | 14150 SW KARL BRAUN DR PO BOX 500 | BEAVERTON OR 97077-0001 |
| 83385 | MICRODOT MFG INC GREER-CENTRAL DIV | 3221 W BIG BEAVER RD | TROY MI 48098 |
| 83486 | ELCO INDUSTRIES INC | 1101 SAMUELSON RD | ROCKFORD IL 61101 |
| 92101 | SCHULZE MFG | 50 INGOLD RD | BURLINGAME CA 94010-2206 |
| 93907 | TEXTRON INC CAMCAR DIV | 600 18TH AVE | ROCKFORD IL 61108-5181 |

| Fig. & Index No. | Tektronix Part No. | Serial No. Effective Dscont | Qty | 12345 Name & Description | Mfr. Code | Mfr. Part No. |
|------------------------|-----------------------|--------------------------------|-----|--|----------------|-----------------|
| 1-1 | 366-0600-00 | | 4 | PUSH BUTTON:0.269 X 0.409,ABS | TK1163 | ORDER BY DESC |
| -2 | 366-1058-00 | | 1 | KNOB:GRAY,0.625 X 0.255 X 0.485 (ATTACHING PARTS) | 0JR05 | ORDER BY DESC |
| -3 | 214-1095-00 | | 1 | PIN,SPRING:0.187 L X 0.094 OD,STL (END ATTACHING PARTS) | 22599 | 52-022-094-0187 |
| -4 | 105-0076-04 | | 1 | RELEASE BAR,LCH:PLUG-IN UNIT | 0JR05 | ORDER BY DESC |
| -5 | 214-1280-00 | | 1 | SPRING,HLCPS:0.14 OD X 1.126 L,TWIST LOOP | 8X345 | ORDER BY DESC |
| -6 | 214-1054-00 | | 1 | SPRING,FLAT:0.825 X 0.322,SST | TK1326 | ORDER BY DESC |
| -7 | 105-0075-00 | | 1 | BOLT,LATCH:7A & 7B SER PL-IN | 80009 | 105007500 |
| -8 | 333-3790-00 | | 1 | PANEL,FRONT:11A16 (ATTACHING PARTS) | 0KB 0 5 | ORDER BY DESC |
| -9 | 211-0392-00 | | 4 | SCREW,MACHINE:4-40 X 0.25,FLH,STL,T-8 (END ATTACHING PARTS) | 93907 · | ORDER BY DESC |
| -10 | 348-0235-00 | | 1 | SHLD GSKT,ELEK:FINGER TYPE,4.734 L, | 92101 | ORDER BY DESC |
| -11 | 386-5219-00 | | 1 | SUBPANEL, FRONT: 11A44 | TK1465 | ORDER BY DESC |
| -12 | 670-9336-00 | | 2 | CIRCUIT BD ASSY:FRONT PANEL (SEE A2,A3, EXCHANGE ITEM) | 80009 | 670933600 |
| -13 | 610-0777-00 | | 2 | CONNECTOR ASSY:11A16 (A1J1001,A1J1002) (ATTACHING PARTS) | 80009 | 610077700 |
| -14 | 210-0405-00 | | 2 | NUT,PLAIN,HEX:2-56 X 0.188,BRS | 73743 | 12157-50 |
| -15 | 211-0413-00 | | 12 | SCREW,MACHINE:2-56 X 0.375,FLH,82 DEG,STL (END ATTACHING PARTS) | 93907 | 221-00995-024 |
| -16 | 210-0259-00 | | 2 | TERMINAL,LUG:0.099 ID,LOCKING,BRS | TK1572 | ORDER BY DESC |
| -17 | 386-6023-00 | • | 1 | PLATE, CONN MT:ALUMINUM | TK1943 | ORDER BY DESC |
| -18 | 174-0159-00 | | 2 | CA ASSY,SPELEC:6,26 AWG,3.0 L,RIBBON (A1J1040,A1J1080) | TK1967 | ORDER BY DESC |
| -19 | 426-2061-00 | | 1 | FR SECT,PLUG-IN:LOWER,ALUMINUM | TK1465 | ORDER BY DESC |
| -20 | 211-0392-00 | | 2 | SCREW,MACHINE:4-40 X 0.25,FLH,STL,T-8 (END ATTACHING PARTS) | 93907 | ORDER BY DESC |
| -21 | 334-3540-00 | | 1 | MARKER, IDENT: MARKED WARNING | TK0860 | ORDER BY DESC |
| -22 | 151-0391-00 | | 2 | TRANSISTOR:DARLINGTON,PNP,SI (A1Q601,A1Q691) | 04713 | MPS-U95 |
| | 342-0937-00 | | 4 | INSULATOR,XSTR:BERGQUIST SIL-PA K-10 | 2K262 | ORDER BY DESC |
| -23 | 151-0390-00 | | 2 | TRANSISTOR:DARLINGTON,NPN,SI (A1Q600,A1Q690) (ATTACHING PARTS) | 04713 | MPS-U45 |
| -24 | 211-0022-00 | | 4 | SCREW,MACHINE:2-56 X 0.188,PNH,STL | TK0435 | ORDER BY DESC |
| -25 | 210-1156-00 | | 4 | WASHER, SHLDR: 0.09 ID X 0.2 OD X 0.085 D, NYL | 80009 | 210115600 |
| -26 | 210-0994-00 | | 4 | WASHER,FLAT:0.125 ID X 0.25 OD X 0.022,STL (END ATTACHING PARTS) | 12327 | ORDER BY DESC |
| -27 | 407-3676-00 | | 1 | BRACKET,HT SK:ALUMINUM (ATTACHING PARTS) | 5Y400 | ORDER BY DESC |
| -28 | 211-0392-00 | | 4 | SCREW,MACHINE:4-40 X 0.25,FLH,STL,T-8 (END ATTACHING PARTS) | 93907 | ORDER BY DESC |
| -29 | 407-3363-00 | | 1 | BRACKET,HEAT SK:ALUMINUM (ATTACHING PARTS) | TK1943 | ORDER BY DESC |

| Fig. & Index | Tektronix | Serial | No. | | | Mfr. | |
|-----------------|--|--------------------|---------|-------------|--|----------------------------------|--|
| No. | Part No. | Effective | Dscont | Qty | 12345 Name & Description | Code | Mfr. Part No. |
| -30 | 211-0711-00 | | | 2 | SCR,ASSEM WSHR:6-32 X 0.25,PNH,STL,T15 (END ATTACHING PARTS) | 0KB01 | ORDER BY DESC |
| -31 | 671-1448-00 | | | 1 | CIRCUIT BD ASSY:MAIN (SEE A1, EXCHANGE ITEM) | 8000 9 | 671144800 |
| -32 | 165-2089-06 | | | 2 | MICROCKT,LINEAR:VERT PREAMP,200 OHM | 80009 | 165208906 |
| -33 | 214-3785-00 | | | 2 | HEAT SINK,ELEC:ALUMINUM (ATTACHING PARTS) | 80009 | ORDER BY DESC |
| -34 | 211-0391-00 | | | 8 | SCREW,MACHINE:2-56 X 0.437,P4,STL,T-8 (END ATTACHING PARTS) | 83486 | ORDER BY DESC |
| -35 | 156-2625-00 | | | 1 | MICROCKT,DGTL:NMOS,CUSTOM,SENES (A1U850) | 66302 | VF4124RC CC0001 |
| -36 | 670-8986-00 | | | 2 | CIRCUIT BD ASSY:SAMPLE/HOLD (SEE A1A1,A1A2, EXCHANGE ITEM) | 80009 | 670898600 |
| -37 | 131-0993-00 | | | 3 | BUS,CONDUCTOR:SHUNT/SHORTING (A1J980,A1J990,A1J992) | 22526 | 65474-006 |
| -38 | 159-0235-00 | | | 2 | FUSE,WIRE LEAD:0.75A,125V,FAST (A1F500,A1F610) | 71400 | TR/MCR 3/4 |
| -39 | 160-6636-00 | | | 1 | MICROCKT,DGTL:CMOS,16 X8 EPROM,PRGM (A1U1080) | 80009 | 160663600 |
| -40 | 671-1451-00 671-1451-01 | B010100 B010155 | B010154 | 2 | CIRCUIT BD ASSY:ATTENUATOR CIRCUIT BD ASSY:ATTENUATOR; (SEE A1A3,A1A4, EXCHANGE ITEM) | 80009 80009 | 671145100 671145101 |
| -41 | 148-0246-00 | | | 8 | RELAY,ARM:2 FORM C 2 COIL LATCH, 5V (K1,K2,K3,K4 ON BOTH A1A3,A1A4) | TK1689 | TQ2EH-L2-5V |
| -42 | 220-0022-00 | | | 6 | NUT BLOCK:0.4 X 0.25 X 0.33,4-40 THRU,NI (ATTACHING PARTS) | 80009 | 220002200 |
| -43 | 211-0409-00 | | | 6 | SCR,ASSEM WSHR:4-40 X 0.312,PNH,STL,T10 (END ATTACHING PARTS) | 93907 | 829-06888-024 |
| -44 | 426-2060-00 | | | 1 | FR SECT,PLUG-IN:UPPER,ALUMINUMN (ATTACHING PARTS) | TK1465 | ORDER BY DESC |
| -45 | 211-0392-00 | | | 2 | SCREW,MACHINE:4-40 X 0.25,FLH,STL,T-8 (END ATTACHING PARTS) | 93907 | ORDER BY DESC |
| -46 | 334-3438-00 | | | 1 | MARKER, IDENT: MARKED TURN OFF POWER | TK0860 | ORDER BY DESC |
| -47 | 214-1061-00 | | | 1 | CONTACT, ELEC: GROUNDING, CU BE | 80009 | 214106100 |
| -48 | 337-1064-11 | | | 2 | SHIELD, ELEC: PLUG-IN SIDE, | 80009 | ORDER BY DESC |
| -49 | 386-5296-00 | | | 1 | PANEL,REAR:POLYCARBONATE (ATTACHING PARTS) | TK1163 | ORDER BY DESC |
| -50 | 213-0904-00 | | | 4 | SCREW,TPG,TR:6-32 X 0.5,PNH,STL (END ATTACHING PARTS) | 83385 | ORDER BY DESC |
| | | | | | STANDARD ACCESSORIES | | |
| | 015-0598-00 015-0601-00 070-7763-00 070-7764-00 | | | 1 1 1 | VOLTAGE ADPTR: 11A16 ADAPTER: 1 TURN CURRENT LOOP MANUAL, TECH: USERS REFERENCE, 11A16 MANUAL, TECH: SERVICE REFERENCE, 11A16 | 80009 03888 80009 80009 | 015059800 P/N VNPRT:JA-11 070776300 070776400 |

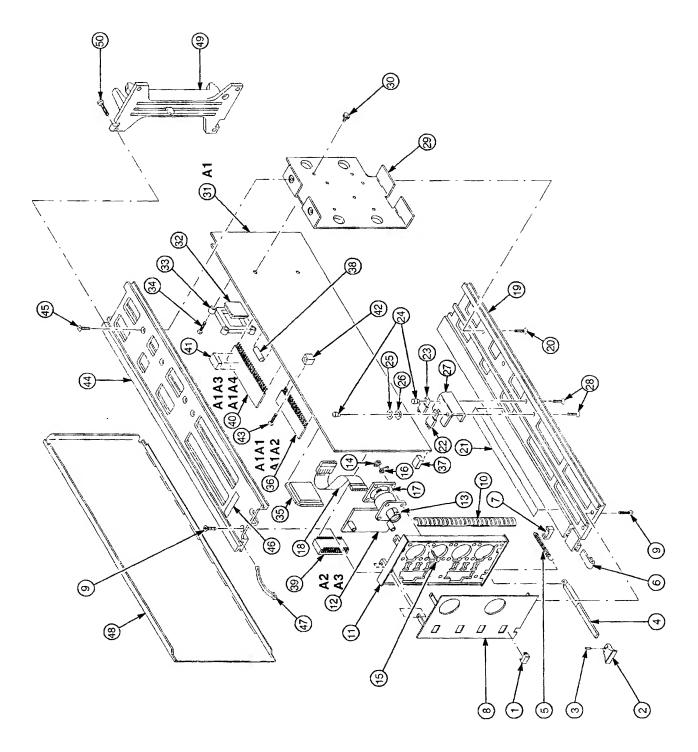


Figure 5-1 — Exploded View of the 11A16 Two Channel Current Amplifier



REVISION INFORMATION

Manual Part No. 070-7764-00 First Printing January 1991

Product: 11A16 Service Manual Revised October 1991

Manual Insert Status

DATE CHANGE REFERENCE STATUS

12 MAR 92

C6-0392

Effective

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14 A. 8

Mainframe Compatibility

The 11A16 amplifier is designed for use in 11300, 11400, DSA 600, and some CSA Series mainframes; it is not compatible with 11800 Series mainframes. Many performance parameters, such as vertical accuracy, and some functions, such as channel deskew, depend on the mainframe and probes used. Detailed performance specifications for different systems are included in the System Specifications section at the end of this manual.

Mainframe Firmware

The 11A16 Amplifier will work best when your mainframe has an updated firmware version. However, your mainframe will operate properly with the 11A16 when the firmware versions listed in Table1-1 are installed in your mainframe.

Table 1-1 — Mainframe Firmware Compatibility

| Mainframe | Firmware Version | | |
|-----------------|------------------|--|--|
| 11301/11302 | 2.4 or later | | |
| 11301A/11302A | 1.0 or later | | |
| 11401/11402 | 4.X or later | | |
| 11402A/11403 | 2.2 or later | | |
| 11403A, CSA 404 | 3.0 or later | | |
| DSA 601/DSA 602 | 1.1 or later | | |

Contact your Tektronix field office for the most recent firmware version for your mainframe.

Degauss in 11300 Series—If you change any 11A16 settings during the two second probe Degauss process, it can result in a **Plugin Communication Failure** error which is displayed. The error occurs because the 11A16 ignores mainframe requests during deskew. Commands sent to the 11A16 over the ASCII interface can also produce this error.

ADD NOV 1988When degauss is complete, the 11A16 is fully operational. If an error does occur it can be easily cleared after degauss by changing any 11A16 setting.

Probe Calibration and Deskew

When you select the probe calibration function **Probes** from the mainframe UTILITY menu, the mainframe performs vertical probe calibration and time deskew on the channel you select. Calibration adjusts sensitivity and offset parameters for greatest accuracy. Then the deskew operation attempts to match the time delay between the selected channels.

The deskew operation of most mainframes will correct for delay differences up to 15 ns between channels. This delay includes the cable propagation time and rise time of the probes and amplifiers. If the delay difference between channels is greater than 15 ns, a complete automated deskew will not be possible. Refer to *Probe Operation* on page 2-5 for detailed information on probe degauss, calibration and deskew.

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Certain mainframes have unique deskew limitations as follows:

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11300 Series—The deskew range is ± 0.5 ns, which is insufficient to accommodate the delays in the 11A16 and current probes.

fredman Israel of

DSA600 Series—In addition to the \pm 15 ns compensation limit between channels, deskew can fail when the 11A16 is in the LEFT compartment, interleaved sampling is invoked (1 or 2 GSample/second), and you attempt to deskew a current probe. During deskew calibration, in this configuration, the digitizer Interleave algorithm performs a rise time measurement on the current probe signal looking for a rise time of 3 ns or less. The low-bandwidth current probes will fail this rise time test and cause the deskew operation to terminate. Installing the 11A16 Amplifier in the CENTER or RIGHT compartment resolves this problem.

Refer to the Tektronix Corporate Catalog for complete information about compatibility of amplifiers and mainframes.

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SEND TO: TEKTRONIX, INC.

LAB INSTRUMENTS MARKETING SUPPORT

P.O. BOX 500, DEL STA 39-327
BEAVERTON, OREGON 97077

11000-SERIES OSCILLOSCOPE PROBLEM REPORT

| Α | INSTRUMENT CONFIGURATION | З | . a.a. | The desire mangens | |
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| PHONE: SUBMITTED BY: | D.77 | | IS THE F ☐ Yes | □ No | ☐ Intermitter |

DESCRIPTION OF PROBLEM:

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D

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LIST ENCLOSURES:



Instructions For Completing The Problem Report

I. Please type or print clearly. Use a separate Problem Report (PR) for each problem.

II. SECTION A

Fill in the instrument configuration table, including all plug-in units, modules, and probes installed in the oscilloscope. The information can be found in one of the menus under the UTILITY major menu.

Instrument: Write the instrument name (e.g., 11301, 11401, 11A32, etc.).

Section (Microprocessor Subsystem): If the instrument has more than one section write the section name. For plug-ins, write in which mainframe slot they are located (e.g., left, center, right).

ROM (Version): Write the rom version number for each instrument and section. Instruments with more than one section will have more than one version number.

ID# (Serial Number): Write the serial number for each instrument. At the factory the ID number is programmed to be the instrument's serial number. If this value has been changed, please write the serial number physically attached to the instrument (mainframes: front panel, plug-in units: top rail).

III. SECTION B

Use the complete company mailing address. Include the name and phone number of the person reporting the error. Also, be sure to fill in the name of the person submitting the PR.

IV. SECTION C

Check the reason for the report and whether the problem is reproducible. We cannot fix a problem when we cannot reproduce the problem condition.

V. SECTION D

Give a complete description of the system configuration on which the problem occurred. Include related peripherals, interfaces, options, special switch and/or strap settings and operating system.

VI. SECTION E

Describe the problem completely. Include any information which might help in evaluating the error with the PR. If you have determined a procedure to avoid the error condition, please include this procedure. If this problem prevents you from accomplishing any useful work with the product, please state this fact. Be sure to include with the PR any information (programs, listings, hard copies, etc.) which will help us duplicate your problem.

VII. SECTION F

This section is for use by Tektronix Lab Instruments Marketing Support personnel. DO NOT WRITE IN THIS SPACE.

VIII. Mail all copies of the Problem Report to:

TEKTRONIX, INC. LAB INSTRUMENTS MARKETING SUPPORT P.O. BOX 500, DEL STA 39-327 BEAVERTON, OREGON 97077

| INTERNAL USE ONLY (DO NOT WRITE BELOW THIS LIN | IE) |
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